



HY17M26

Datasheet

8-Bit RISC-like Mixed Signal Microcontroller
Embedded 24-Bit $\Sigma\Delta$ ADC

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1. Feature

- **8-Bit RISC-like Mixed Signal Microcontroller**
 - 71 high performance H08D instruction sets
 - Hardware Lookup table
 - Power On/ Brown Out 1/ Brown Out 2
 - WDT/MCLR Reset
- **Operating Voltage and Temperature Range**
 - Digital Circuit: 1.9V ~ 5.5V
 - Analog Circuit: 2.4V ~ 5.5V
 - Operating Temperature : - 40°C ~ 85°C
- **Memory**
 - 8K words MTP Program Memory
(Write/Erase cycle times: 100 cycles)
 - 128 words Build-In EPROM(BIE) Data Memory
(Write/Erase cycle times: 100 cycles)
 - 640 bytes SRAM
 - 8 Level Stack
- **24-Bit Σ ADC Analog to Digital Converter**
 - Max. Sampling Frequency up to 1MHz
 - Oversampling Freq. setting: 64 ~ 65536
 - Second/third order comb filter with conversion frequency of 15.6Ksps
 - ADC Gain: x1/4, x1/2, x1,x2,x4,x8,x16
 - Differential input signal and zero adjustment of measurement range
 - Low temperature drift coefficient and built-in absolute temperature sensor
- **Low Power and Low Temperature Drift Coefficient Power System**
 - VDDA Linear regulated power supply
 - ◆ Supply analog circuit or external sensor voltage source
 - ◆ Design of external Input Voltage
 - ◆ Regulated output can be set 2.4V/2.6V/2.9V/3.3V /3.6V /4.0V/4.5V/5.0V
- **Communication interface**
 - 2* I²C, 2* EUART, SPI communication interface
 - 2-wire ICE, programming pin supply On Chip Debug (OCD) and In Application Programming (IAP)
- **Timer**
 - Watch Dog
 - 2* 8-bit Timer A,(TMA1/TMA2)
 - 2* 16-bit Timer B(TMB1/TMB2)
 - ◆ 2ch 16-Bit PWM or 4ch 8-bit PWM
 - 2* Timer C supply capture function
- **Low Power Consumption**
 - Sleep Mode: 0.1uA@3.0V
 - Idle Mode: 0.5uA@3.0V
 - Wake up in Idle mode, support HAO quick start (wake up time 25uS@2MHz, 3V)
- **Bootloader**
 - Support ISP (In-System Programming) function
- **Operating Frequency**
 - Built-in $\pm 2\%$ @25°C high accuracy HAO oscillator (After burner calibration)
 - Built-in HAO oscillator, four HAO frequency can be selected: 1.843MHz, 4.147MHz, 8.755MHz, 17.51MHz
 - Built-in low power LPO oscillator 14.5KHz
 - External Crystal oscillator: 32768Hz ~ 16MHz
- **Package Type**
 - SSOP16 、SSOP28 、QFN32
- **Application Field**
 - Bridge Pressure Sensor
 - Analog Signal Collector

Function List

Model No.	VDD (V)	Internal Clock (Hz)	System Clock (Hz)	Program Memory (word)	SRAM (byte)	Built-In EPROM (word)	ADC ENOB (bit x ch)	Sample Rate (sps)	I/O	Timer (bit x ch)	PWM (bit x ch)	Serial Interface (I/F x ch)	Package
HY17M26	1.9~ 5.5	14.5K	14.5K~16M	8K	640	128	21-bit x10	8~15.6K	9xIO	8-bit x 2 16-bit x 2	8-bit x 4 16-bit x 2	EUART x 2 I ² C x 2 SPI x 1	SSOP16
		1.843M					21-bit x18		21xIO				SSOP28
		4.147M					21-bit x18		23xIO				QFN32
		8.755M											
		17.51M											

2. Pin Definition

2.1. Pin Diagram

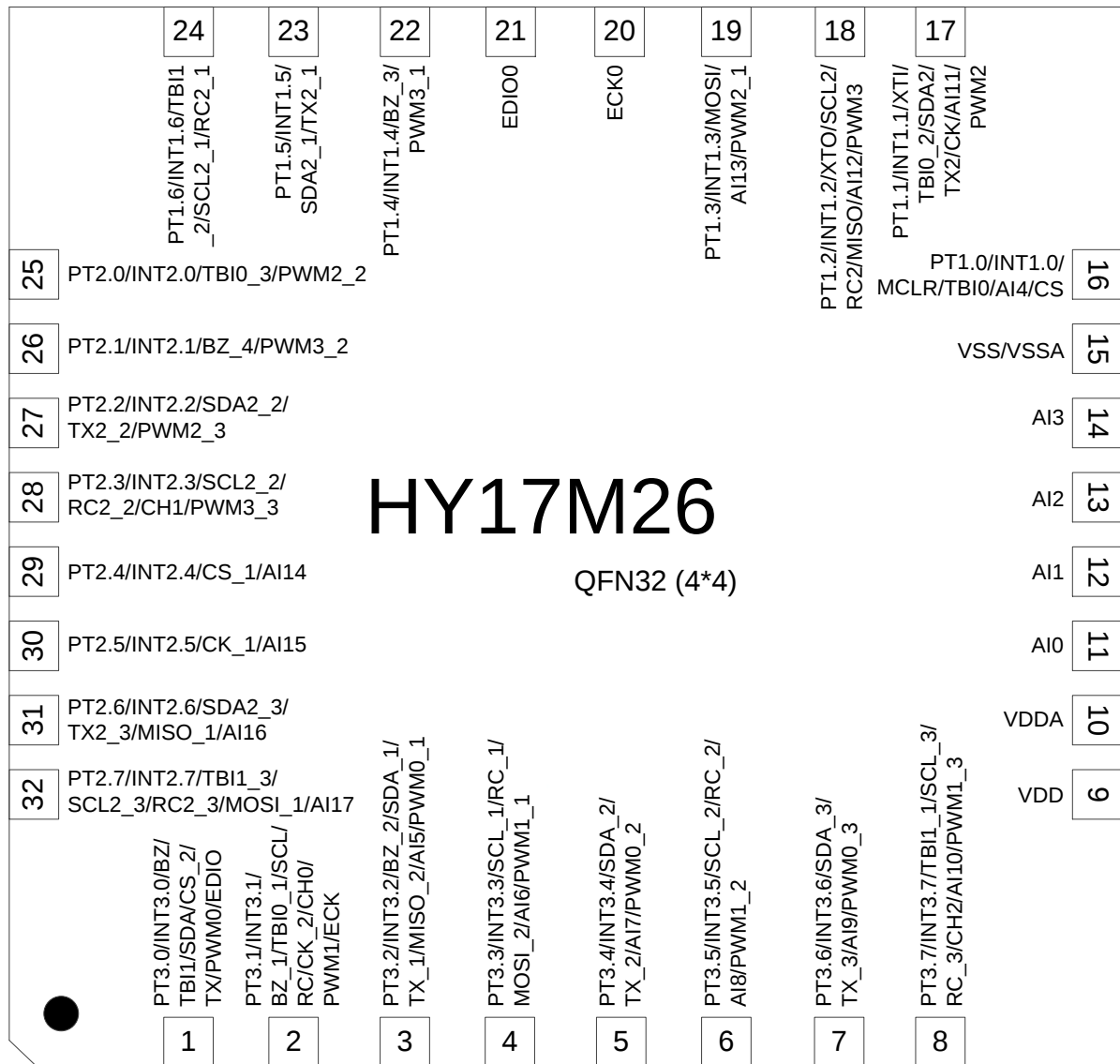


Figure 2-1 QFN32(4*4) Pin Diagram

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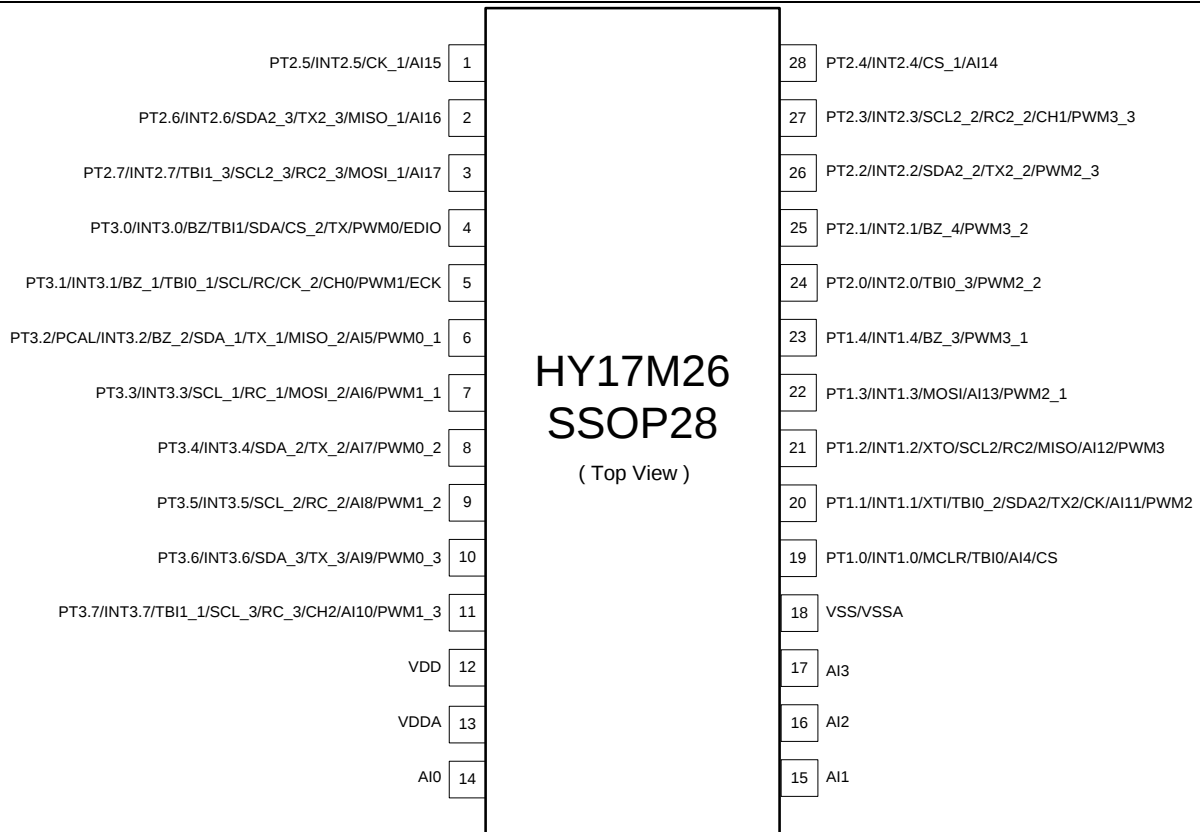


Figure 2-2 SSOP28 Pin Diagram

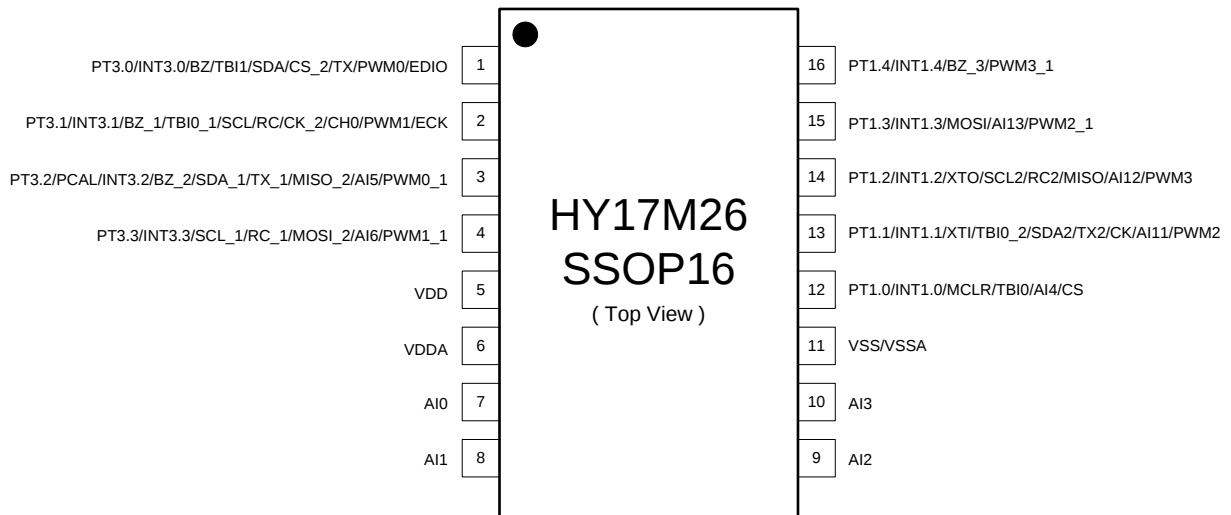


Figure 2-3 SSOP16 Pin Diagram

2.2. Pinout I/O Description

“I/O” Input/Output, “I” Input, “O” Output, “S” Smith triggers, “C” CMOS, “P” Power Source, “A” Analog channel

Package / Pin No.			Characteristic			Description
QFN32	SSOP28	SSOP16	Pin Name	Type	Buffer	
1	4	1	PT3.0/INT3.0/BZ/TBI1/SDA/CS_2*2/TX/PWM0/EDIO*1			
			PT3.0	I/O	S/C	Digital Input/Output Port
			INT3.0	I	S	External Interrupt Input
			BZ	O	C	Buzzer Signal Output pin
			TBI1	I	S	TimerB CPI Source Input pin
			SDA	I/O	S/C	I ² C communication interface Data pin
			TX	O	C	UART communication Transfer Pin
			CS_2*2	I	S	SPI communication enable Pin
			PWM0	O	C	PWM0 Output pin
			EDIO*1	I/O	S/C	Emulation / Programming data pin
2	5	2	PT3.1/INT3.1/BZ_1*2/TBI0_1*2/SCL/RC/CK_2*2/CH0/PWM1/ECK*1			
			PT3.1	I/O	S/C	Digital Input/Output Port
			INT3.1	I	S	External Interrupt Input
			BZ_1*2	O	C	Buzzer Signal Output pin
			TBI0_1*2	I	S	TimerB CPI Source Input pin
			SCL	I/O	S/C	I ² C communication interface Data pin
			RC	I	S	UART communication Receiver Pin
			CK_2*2	I/O	S/C	SPI communication Clock Pin
			CH0	A	A	Comparator Input Channel
			PWM1	O	C	PWM1 Output pin
			ECK*1	I	S	Emulation / Programming clock pin
3	6	3	PT3.2/PCAL/INT3.2/BZ_2*2/SDA_1*2/TX_1*2/MISO_2*2/AI5/PWM0_1*2			
			PT3.2	I/O	S/C	Digital Input/Output Port
			PCAL*1	O	C	Frequency calibration output pin for programming
			INT3.2	I	S	External Interrupt Input
			BZ_2*2	O	C	Buzzer Signal Output pin
			SDA_1*2	I/O	S/C	I ² C communication interface Data pin
			TX_1*2	O	C	UART communication Transfer Pin
			MISO_2*2	I/O	S/C	SPI communication Data Pin (Master input, Slave Output)
			AI5	A	A	Analog Input Channel
			PWM0_1*2	O	C	PWM0 Output pin
4	7	4	PT3.3/INT3.3/SCL_1*2/RC_1*2/MOSI_2*2/AI6/PWM1_1*2			
			PT3.3	I/O	S/C	Digital Input/Output Port

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Package / Pin No.			Characteristic			Description
QFN32	SSOP28	SSOP16	Pin Name	Type	Buffer	
			INT3.3	I	S	External Interrupt Input
			SCL_1 ^{*2}	I/O	S/C	I ² C communication interface Data pin
			RC_1 ^{*2}	I	S	UART communication Receiver Pin
			MOSI_2 ^{*2}	I/O	S/C	SPI communication Data Pin (Master Output, Slave Input)
			AI6	A	A	Analog Input Channel
			PWM1_1 ^{*2}	O	C	PWM1 Output pin
5	8	-	PT3.4/INT3.4/TCI1_2 ^{*2} /SDA_2 ^{*2} /TX_2 ^{*2} /AI7/PWM0_2 ^{*2}			
			PT3.4	I/O	S/C	Digital Input/Output Port
			INT3.4	I	S	External Interrupt Input
			TCI1_2 ^{*2}	I	S	Timer C Input pin
			SDA_2 ^{*2}	I/O	S/C	I ² C communication interface Data pin
			TX_2 ^{*2}	O	C	UART communication Transfer Pin
			AI7	A	A	Analog Input Channel
			PWM0_2 ^{*2}	O	C	PWM0 Output pin
6	9	-	PT3.5/INT3.5/TCI2_2 ^{*2} /SCL_2 ^{*2} /RC_2 ^{*2} /AI8/PWM1_2 ^{*2}			
			PT3.5	I/O	S/C	Digital Input/Output Port
			INT3.5	I	S	External Interrupt Input
			TCI2_2 ^{*2}	I	S	Timer C Input pin
			SCL_2 ^{*2}	I/O	S/C	I ² C communication interface Data pin
			RC_2 ^{*2}	I	S	UART communication Receiver Pin
			AI8	A	A	Analog Input Channel
			PWM1_2 ^{*2}	O	C	PWM1 Output pin
7	10	-	PT3.6/INT3.6/TBI2_2 ^{*2} /SDA_3 ^{*2} /TX_3 ^{*2} /AI9/PWM0_3 ^{*2}			
			PT3.6	I/O	S/C	Digital Input/Output Port
			INT3.6	I	S	External Interrupt Input
			TBI2_2 ^{*2}	I	S	TimerB CPI Source Input pin
			SDA_3 ^{*2}	I/O	S/C	I ² C communication interface Data pin
			TX_3 ^{*2}	O	C	UART communication Transfer Pin
			AI9	A	A	Analog Input Channel
			PWM0_3 ^{*2}	O	C	PWM0 Output pin
8	11	-	PT3.7/INT3.7/TBI1_1 ^{*2} /SCL_3 ^{*2} /RC_3 ^{*2} /CH2/AI10/PWM1_3 ^{*2}			
			PT3.7	I/O	S/C	Digital Input/Output Port
			INT3.7	I	S	External Interrupt Input
			TBI1_1 ^{*2}	I	S	TimerB CPI Source Input pin
			SCL_3 ^{*2}	I/O	S/C	I ² C communication interface Data pin
			RC_3 ^{*2}	I	S	UART communication Receiver Pin

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Package / Pin No.			Characteristic			Description
QFN32	SSOP28	SSOP16	Pin Name	Type	Buffer	
			CH2	A	A	Comparator Input Channel
			AI10	A	A	Analog Input Channel
			PWM1_3*2	O	C	PWM1 Output pin
9	12	5	VDD	P	P	Chip Power Voltage Input, an external 10uF capacitor is required.
10	13	6	VDDA	P	P	Regulator Output, analog circuit voltage source, an external 1uF capacitor is required.
11	14	7	AI0	A	A	Analog Input Channel
12	15	8	AI1	A	A	Analog Input Channel
13	16	9	AI2	A	A	Analog Input Channel
14	17	10	AI3	A	A	Analog Input Channel
15	18	11	VSS	P	P	Chip Power Ground
15	18	11	VSSA	P	P	Chip Analog Power Ground
16	19	12	PT1.0/INT1.0/MCLR/TBI0/AI4/CS			
			PT1.0	I/O	S/C	Digital Input/Output Port
			INT1.0	I	S	External Interrupt Input
			MCLR	I	S	External Reset pin with internal pull-up resistor, activated low.
			TBI0	I	S	TimerB CPI Source Input pin
			CS	I	S	SPI communication enable Pin
			AI4	A	A	Analog Input Channel
17	20	13	PT1.1/INT1.1/XTI/TBI0_2*2/SDA2/TX2/CK/AI11/PWM2			
			PT1.1	I/O	S/C	Digital Input/Output Port
			INT1.1	I	S	External Interrupt Input
			XTI	A	A	External Oscillator Input pin
			TBI0_2*2	I	S	TimerB CPI Source Input pin
			SDA2	I/O	S/C	Second I2C communication interface Data pin
			TX2	O	C	Second UART communication Transfer Pin
			CK	I/O	S/C	SPI communication Clock Pin
			AI11	A	A	Analog Input Channel
			PWM2	O	C	PWM2 Output pin
18	21	14	PT1.2/INT1.2/XTO/TBI2/SCL2/RC2/MISO/AI12/PWM3			
			PT1.2	I/O	S/C	Digital Input/Output Port
			INT1.2	I	S	External Interrupt Input
			XTO	A	A	External Oscillator Output pin
			TBI2	I	S	TimerB CPI Source Input pin
			SCL2	I/O	S/C	Second I ² C communication interface Data pin
			RC2	I	S	Second UART communication Receiver Pin

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Package / Pin No.			Characteristic			Description
QFN32	SSOP28	SSOP16	Pin Name	Type	Buffer	
			MISO	I/O	S/C	SPI communication Data Pin (Master input, Slave Output)
			AI12	A	A	Analog Input Channel
			PWM3	O	C	PWM3 Output pin
19	22	15	PT1.3/INT1.3/TCI1/MOSI/AI13/PWM2_1 ^{*2}			
			PT1.3	I/O	S/C	Digital Input/Output Port
			INT1.3	I	S	External Interrupt Input
			TCI1	I	S	Timer C Input pin
			MOSI	I/O	S/C	SPI communication Data Pin (Master Output, Slave Input)
			AI13	A	A	Analog Input Channel
			PWM2_1 ^{*2}	O	C	PWM2 Output pin
20	-	-	ECK0	I	S	Emulation / Programming clock pin
21	-	-	EDIO0	I/O	S/C	Emulation / Programming data pin
22	23	16	PT1.4/INT1.4/TCI2/BZ_3/PWM3_1 ^{*2}			
			PT1.4	I/O	S/C	Digital Input/Output Port
			INT1.4	I	S	External Interrupt Input
			TCI2	I	S	Timer C Input pin
			BZ_3	O	C	Buzzer Signal Output pin
			PWM3_1 ^{*2}	O	C	PWM3 Output pin
23	-	-	PT1.5/INT1.5/SDA2_1 ^{*2} /TX2_1 ^{*2}			
			PT1.5	I/O	S/C	Digital Input/Output Port
			INT1.5	I	S	External Interrupt Input
			SDA2_1 ^{*2}	I/O	S/C	Second I ² C communication interface Data pin
			TX2_1 ^{*2}	O	C	Second UART communication Transfer Pin
24	-	-	PT1.6/INT1.6/TBI1_2 ^{*2} /SCL2_1 ^{*2} /RC2_1 ^{*2}			
			PT1.6	I/O	S/C	Digital Input/Output Port
			INT1.6	I	S	External Interrupt Input
			TBI1_2 ^{*2}	I	S	TimerB CPI Source Input pin
			SCL2_1 ^{*2}	I/O	S/C	Second I ² C communication interface Data pin
			RC2_1 ^{*2}	I	S	Second UART communication Receiver Pin
25	24	-	PT2.0/INT2.0/TBI0_3 ^{*2} /PWM2_2 ^{*2}			
			PT2.0	I/O	S/C	Digital Input/Output Port
			INT2.0	I	S	External Interrupt Input
			TBI0_3 ^{*2}	I	S	TimerB CPI Source Input pin
			PWM2_2 ^{*2}	O	C	PWM2 Output pin
26	25	-	PT2.1/INT2.1/BZ_4 ^{*2} /PWM3_2 ^{*2}			
			PT2.1	I/O	S/C	Digital Input/Output Port

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Package / Pin No.			Characteristic			Description
QFN32	SSOP28	SSOP16	Pin Name	Type	Buffer	
			INT2.1	I	S	External Interrupt Input
			BZ_4 ^{*2}	O	C	Buzzer Signal Output pin
			PWM3_2 ^{*2}	O	C	PWM3 Output pin
27	26	-	PT2.2/INT2.2/TCI1_1 ^{*2} /SDA2_2 ^{*2} /TX2_2 ^{*2} /PWM2_3 ^{*2}			
			PT2.2	I/O	S/C	Digital Input/Output Port
			INT2.2	I	S	External Interrupt Input
			TCI1_1 ^{*2}	I	S	Timer C Input pin
			SDA2_2 ^{*2}	I/O	S/C	Second I ² C communication interface Data pin
			TX2_2 ^{*2}	O	C	Second UART communication Transfer Pin
			PWM2_3 ^{*2}	O	C	PWM2 Output pin
28	27	-	PT2.3/INT2.3/TCI2_1 ^{*2} /SCL2_2 ^{*2} /RC2_2 ^{*2} /CH1/PWM3_3 ^{*2}			
			PT2.3	I/O	S/C	Digital Input/Output Port
			INT2.3	I	S	External Interrupt Input
			TCI2_1 ^{*2}	I	S	Timer C Input pin
			SCL2_2 ^{*2}	I/O	S/C	Second I ² C communication interface Data pin
			RC2_2 ^{*2}	I	S	Second UART communication Receiver Pin
			CH1	A	A	Analog Input Channel
29	28	-	PT2.4/INT2.4/TBI2_1 ^{*2} /CS_1 ^{*2} /AI14			
			PT2.4	I/O	S/C	Digital Input/Output Port
			INT2.4	I	S	External Interrupt Input
			TBI2_1 ^{*2}	I	S	TimerB CPI Source Input pin
			CS_1 ^{*2}	I	S	SPI communication enable Pin
			AI14	A	A	Analog Input Channel
30	1	-	PT2.5/INT2.5/CK_1 ^{*2} /AI15			
			PT2.5	I/O	S/C	Digital Input/Output Port
			INT2.5	I	S	External Interrupt Input
			CK_1 ^{*2}	I/O	S/C	SPI communication Clock Pin
			AI15	A	A	Analog Input Channel
31	2	-	PT2.6/INT2.6/SDA2_3 ^{*2} /TX2_3 ^{*2} /MISO_1 ^{*2} /AI16			
			PT2.6	I/O	S/C	Digital Input/Output Port
			INT2.6	I	S	External Interrupt Input
			SDA2_3 ^{*2}	I/O	S/C	Second I ² C communication interface Data pin
			TX2_3 ^{*2}	O	C	Second UART communication Transfer Pin
			MISO_1 ^{*2}	I/O	S/C	SPI communication Data Pin (Master input, Slave Output)
			AI16	A	A	Analog Input Channel

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Package / Pin No.			Characteristic			Description
QFN32	SSOP28	SSOP16	Pin Name	Type	Buffer	
32	3	-	PT2.7/INT2.7/TBI1_3*2/SCL2_3*2/RC2_3*2/MOSI_1*2/AI17			
			PT2.7	I/O	S/C	Digital Input/Output Port
			INT2.7	I	S	External Interrupt Input
			TBI1_3*2	I	S	TimerB CPI Source Input pin
			SCL2_3*2	I/O	S/C	Second I ² C communication interface Data pin
			RC2_3*2	I	S	Second UART communication Receiver Pin
			MOSI_1*2	I/O	S/C	SPI communication Data Pin (Master Output, Slave Input)
			AI17	A	A	Analog Input Channel

¹ Debugging, emulation, and read/write chip communication pins. GPIO multiplexing is not available in this mode.

² Through the internal settings of the chip, the multiplexed pin function can be planned to be output or input on this pin. * Indicates the pin selected for multiplexing.

Table 2-1 Pin Definition and Function Description

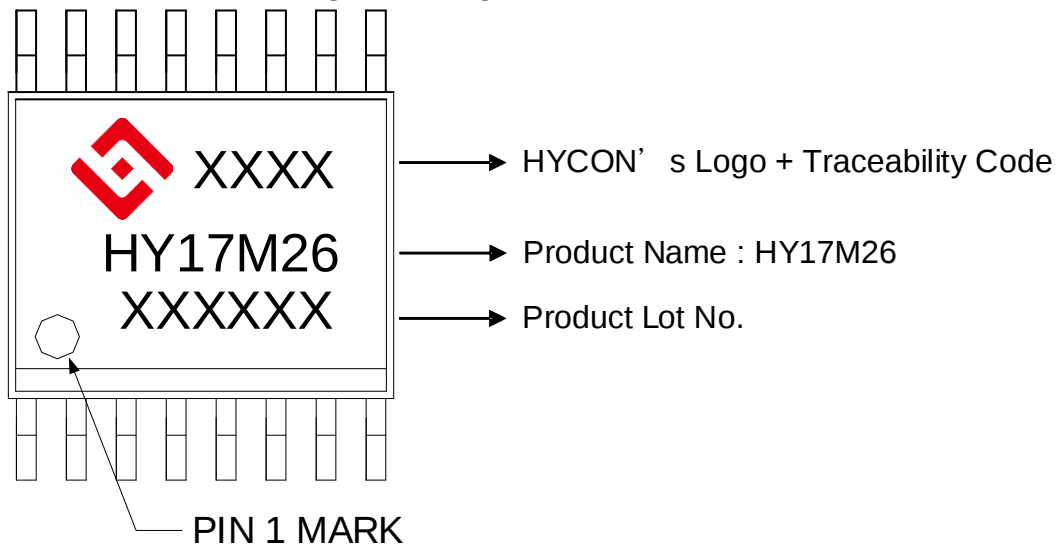
2.3. Multiplexing Pin Definition

Function	I/O Type	INT	Internal Pull high	Special Function	Buzzer	Timer B/C Enable, Input	I ² C	UART	SPI	Comparator	Analog	PWM
AI0	AI	-	-	-	-	-	-	-	-	-	AI0	-
AI1	AI	-	-	-	-	-	-	-	-	-	AI1	-
AI2	AI	-	-	-	-	-	-	-	-	-	AI2	-
AI3	AI	-	-	-	-	-	-	-	-	-	AI3	-
PT1.0	DAI/O	INT1.0	PU1.0	MCLR	-	TBI0	-	-	CS	-	AI4	-
PT1.1	DAI/O	INT1.1	PU1.1	XTI	-	TBI0_2	SDA2	TX2	CK	-	AI11	PWM2
PT1.2	DAI/O	INT1.2	PU1.2	XTO	-	TBI2	SCL2	RC2	MISO	-	AI12	PWM3
PT1.3	DAI/O	INT1.3	PU1.3	-	-	TCI1	-	-	MOSI	-	AI13	PWM2_1
PT1.4	DI/O	INT1.4	PU1.4	-	BZ_3	TCI2	-	-	-	-	-	PWM3_1
PT1.5	DI/O	INT1.5	PU1.5	-	-	-	SDA2_1	TX2_1	-	-	-	-
PT1.6	DI/O	INT1.6	PU1.6	-	-	TBI1_2	SCL2_1	RC2_1	-	-	-	-
PT2.0	DI/O	INT2.0	PU2.0	-	-	TBI0_3	-	-	-	-	-	PWM2_2
PT2.1	DI/O	INT2.1	PU2.1	-	BZ_4	-	-	-	-	-	-	PWM3_2
PT2.2	DI/O	INT2.2	PU2.2	-	-	TCI1_1	SDA2_2	TX2_2	-	-	-	PWM2_3
PT2.3	DAI/O	INT2.3	PU2.3	-	-	TCI2_1	SCL2_2	RC2_2	-	CH1	-	PWM3_3
PT2.4	DAI/O	INT2.4	PU2.4			TBI2_1			CS_1		AI14	
PT2.5	DAI/O	INT2.5	PU2.5						CK_1		AI15	
PT2.6	DAI/O	INT2.6	PU2.6				SDA2_3	TX2_3	MISO_1		AI16	
PT2.7	DAI/O	INT2.7	PU2.7			TBI1_3	SCL2_3	RC2_3	MOSI_1		AI17	
PT3.0	DI/O	INT3.0	PU3.0	EDIO	BZ	TBI1	SDA	TX	CS_2			PWM0
PT3.1	DAI/O	INT3.1	PU3.1	ECK	BZ_1	TBI0_1	SCL	RC	CK_2	CH0		PWM1
PT3.2	DAI/O	INT3.2	PU3.2	PCAL	BZ_2	-	SDA_1	TX_1	MISO_2	-	AI5	PWM0_1
PT3.3	DAI/O	INT3.3	PU3.3	-	-	-	SCL_1	RC_1	MOSI_2	-	AI6	PWM1_1
PT3.4	DAI/O	INT3.4	PU3.4	-	-	TCI1_2	SDA_2	TX_2	-	-	AI7	PWM0_2
PT3.5	DAI/O	INT3.5	PU3.5	-	-	TCI2_2	SCL_2	RC_2	-	-	AI8	PWM1_2
PT3.6	DAI/O	INT3.6	PU3.6	-	-	TBI2_2	SDA_3	TX_3	-	-	AI9	PWM0_3
PT3.7	DAI/O	INT3.7	PU3.7	-	-	TBI1_1	SCL_3	RC_3	-	CH2	AI10	PWM1_3
ECK0	DI/O	-	-	ECK0	-	-	-	-	-	-	-	-
EDIO0	DI/O	-	-	EDIO0	-	-	-	-	-	-	-	-

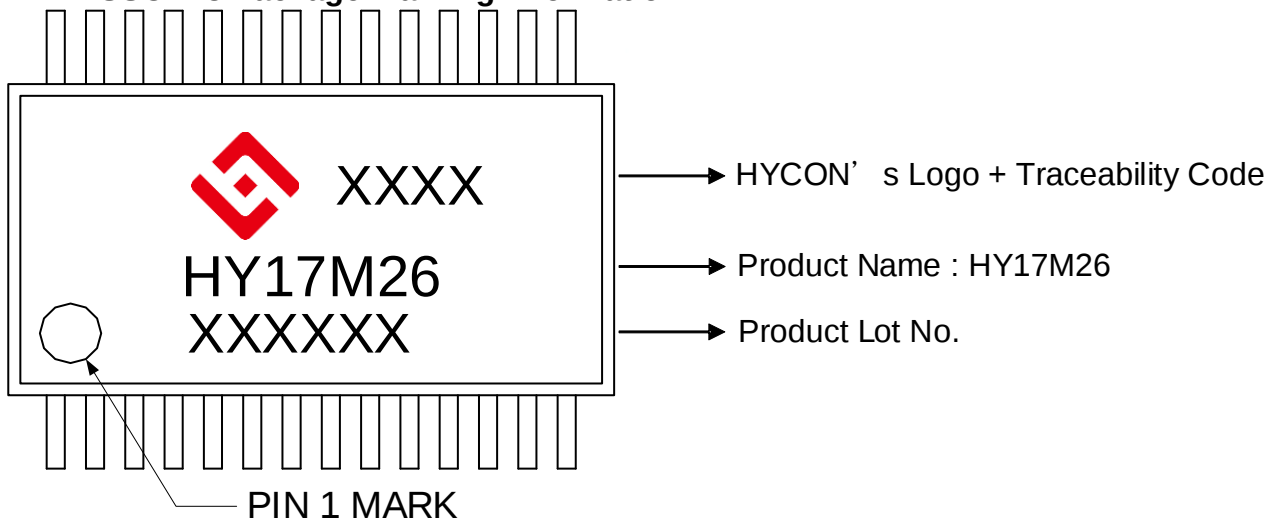
Table 2-2 Pin Definition and Function Description

2.4. Package marking information

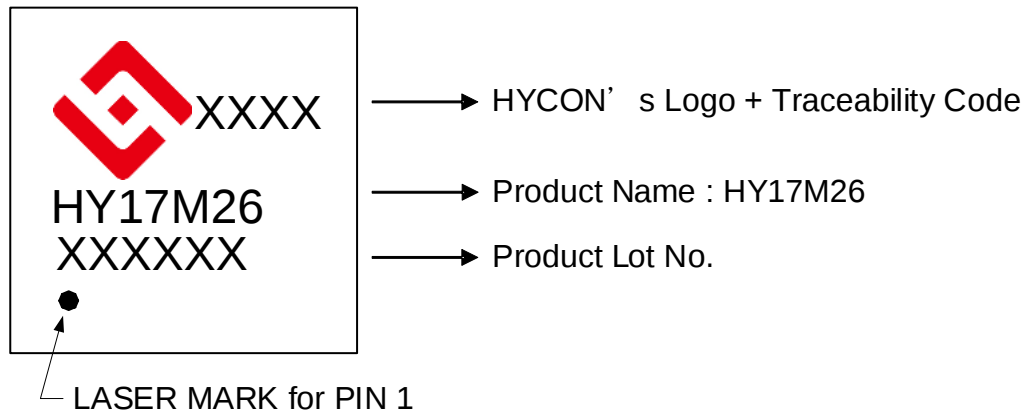
2.4.1. SSOP16 Package marking information



2.4.2. SSOP28 Package marking information



2.4.3. QFN32 Package marking information



3. Application Circuit

3.1. Pressure Sensor Application

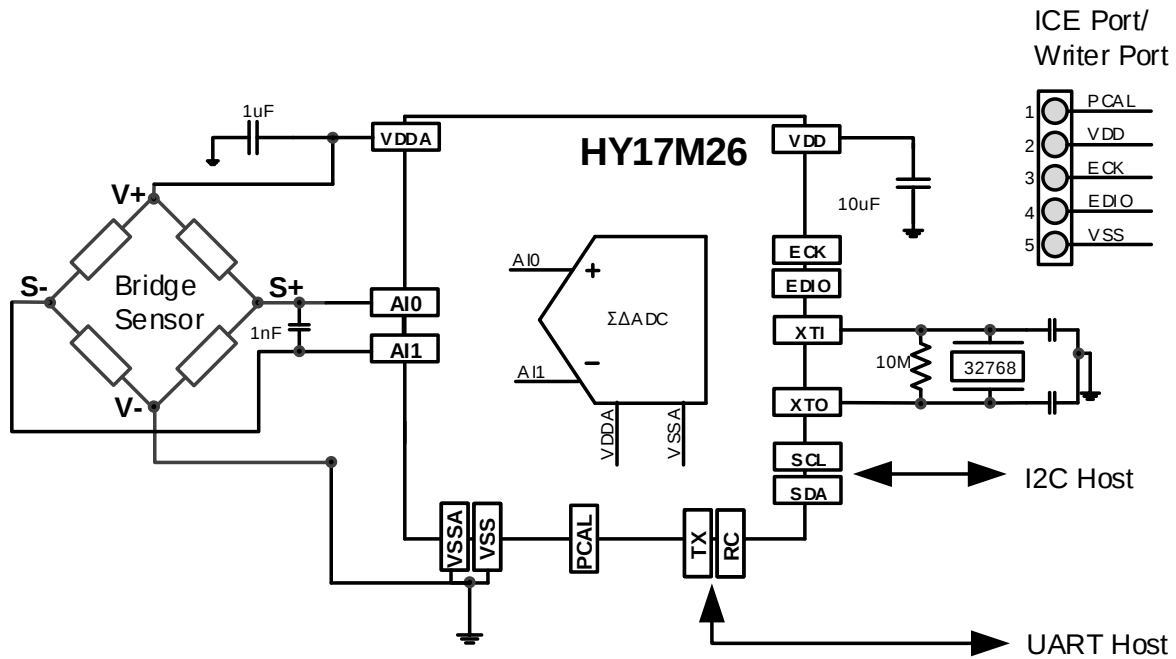


Figure 3-1 Pressure sensor application reference circuit

4. Function Outline

4.1. Block Diagram

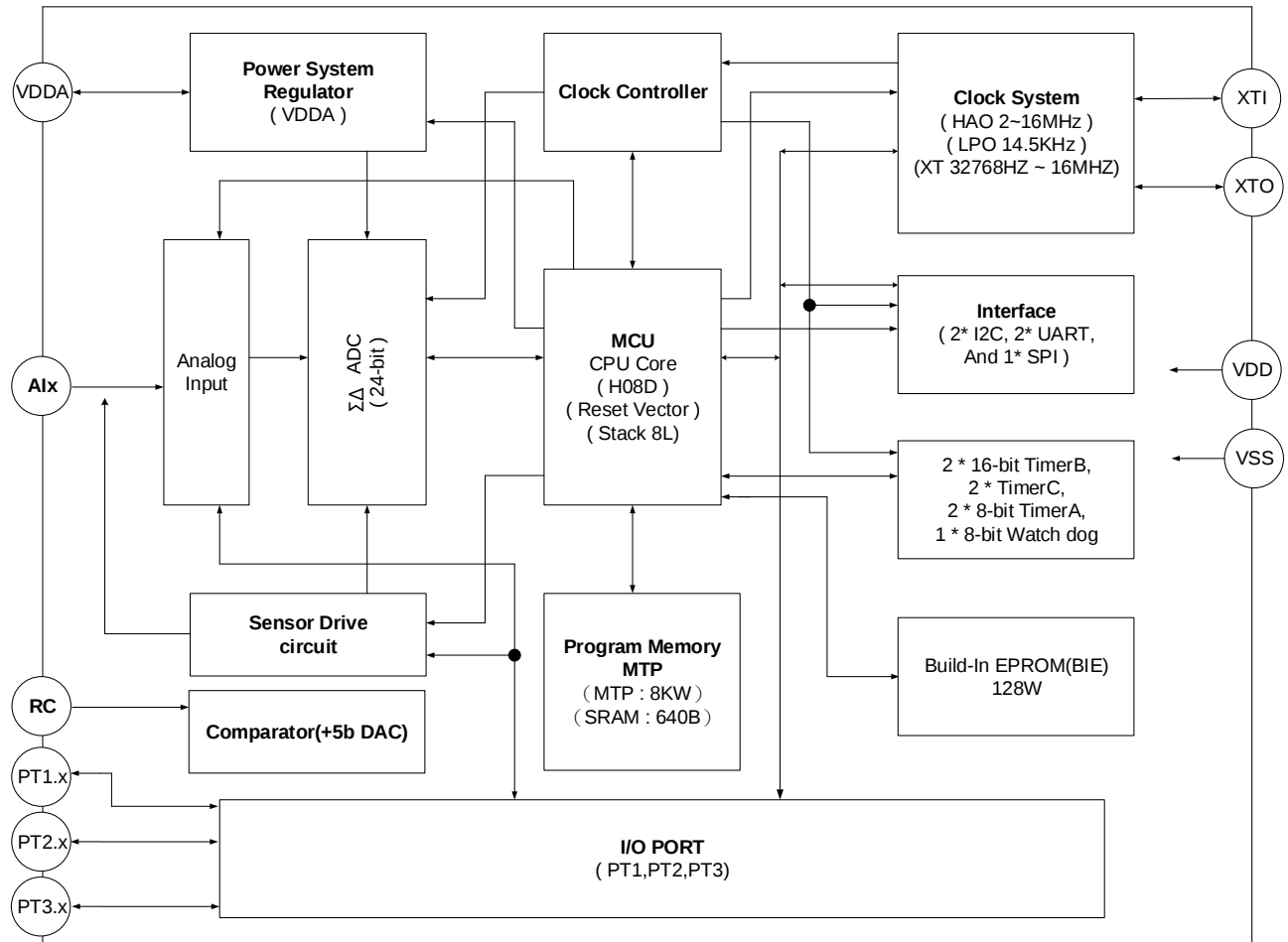


Figure 4-1 HY17M26 Internal Block Diagram

4.2. Related Manuals and Supporting Documents

IC Function Related Instruction Manual

DS-HY17M26

UG-HY17M26

APD-CORE002

APD-HYIDE016

HY17M26 Data Sheet Manual

HY17M26 User's Manual

H08A, H08C, H08D Instruction Set User's Manual

H08 CIDE Software Instruction Manual

Development Tool Related Instruction Manual

APD-HY17MIDE001

APD-HY17MIDE010

HY17M Series Development Tool Software Instruction Manual

HY17M26 Series Development Tool Hardware Instruction Manual

Product Production Related Instruction Manual

APD-HY17MIDE0xx

HY17M26 Series Production Specialized Programmer Manual

4.3. Clock System

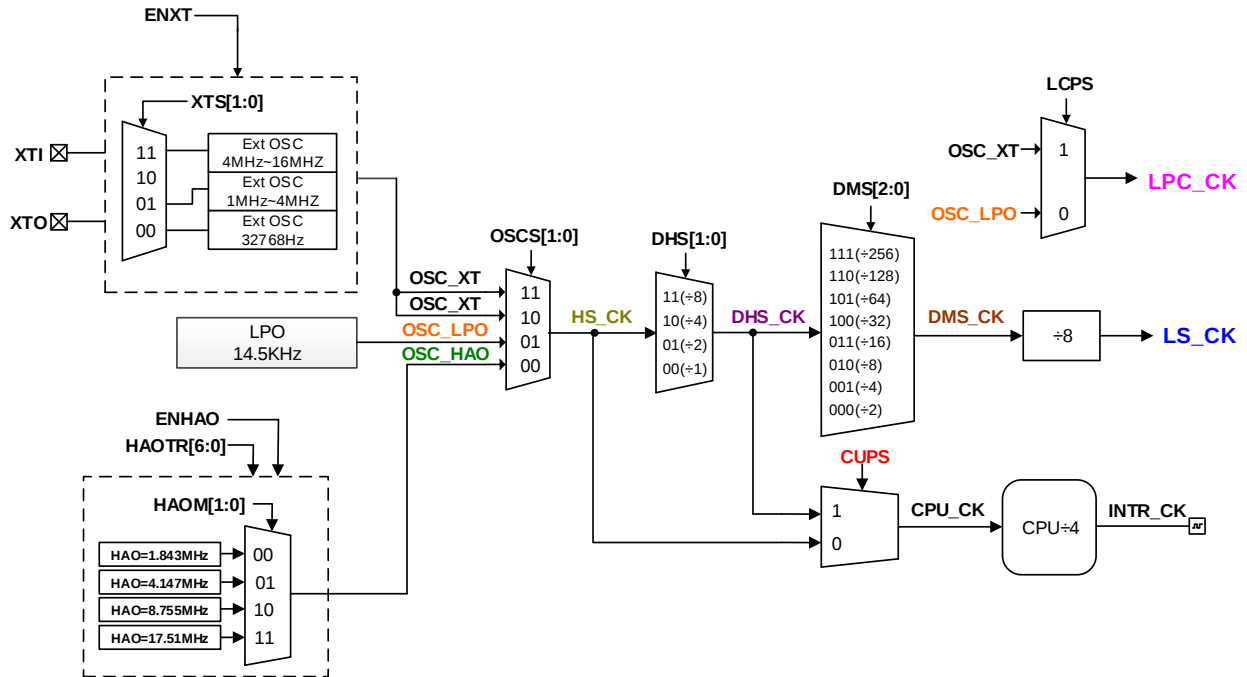


Figure 4-2 Clock System(一)

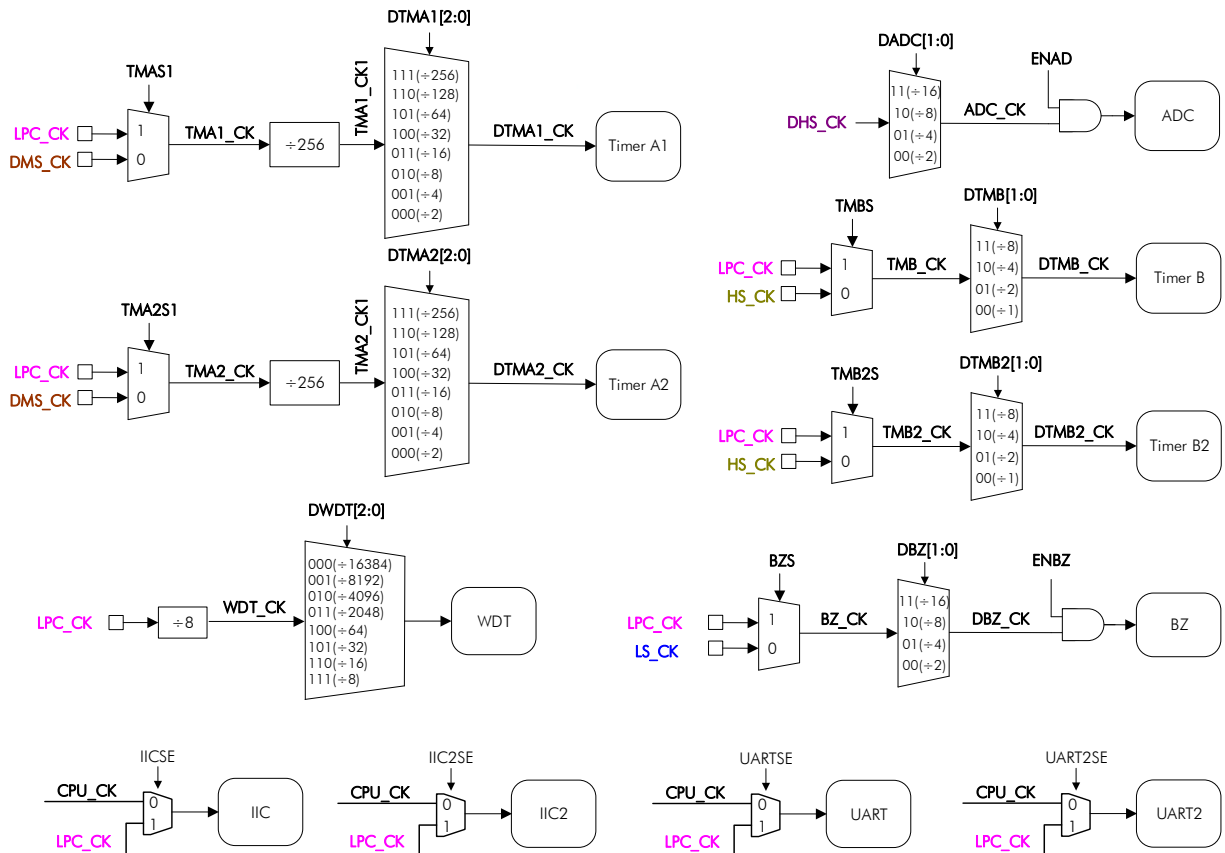


Figure 4-3 Clock System(二)

4.4. GPIO PT1~PT3 System

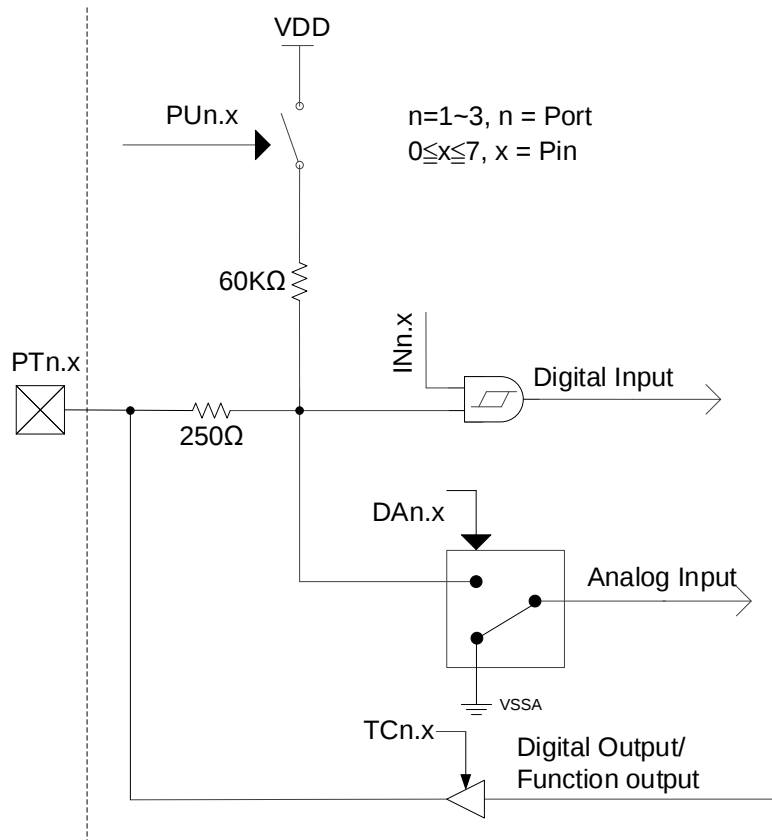


Figure 4-4 GPIO PT1~PT3 System

4.5. Reset System

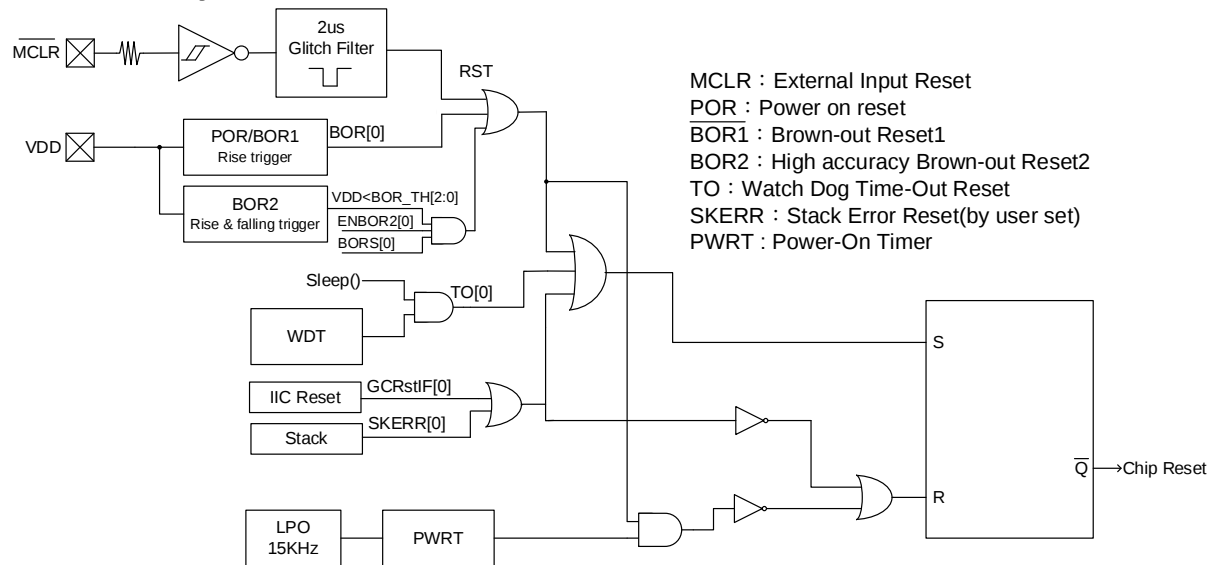


Figure 4-5 Reset

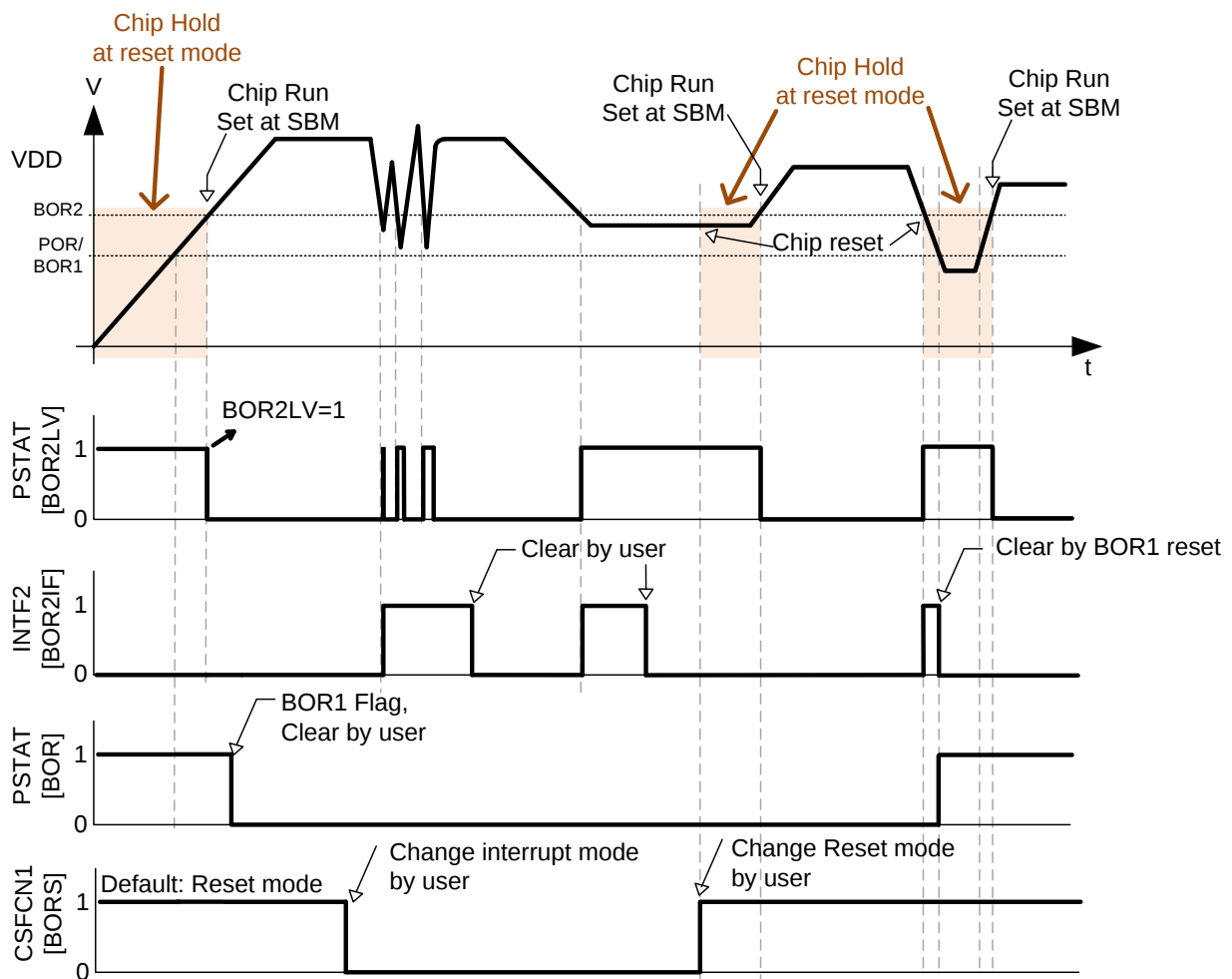


Figure 4-6 BOR1 and BOR2 Chart

4.6. Power System

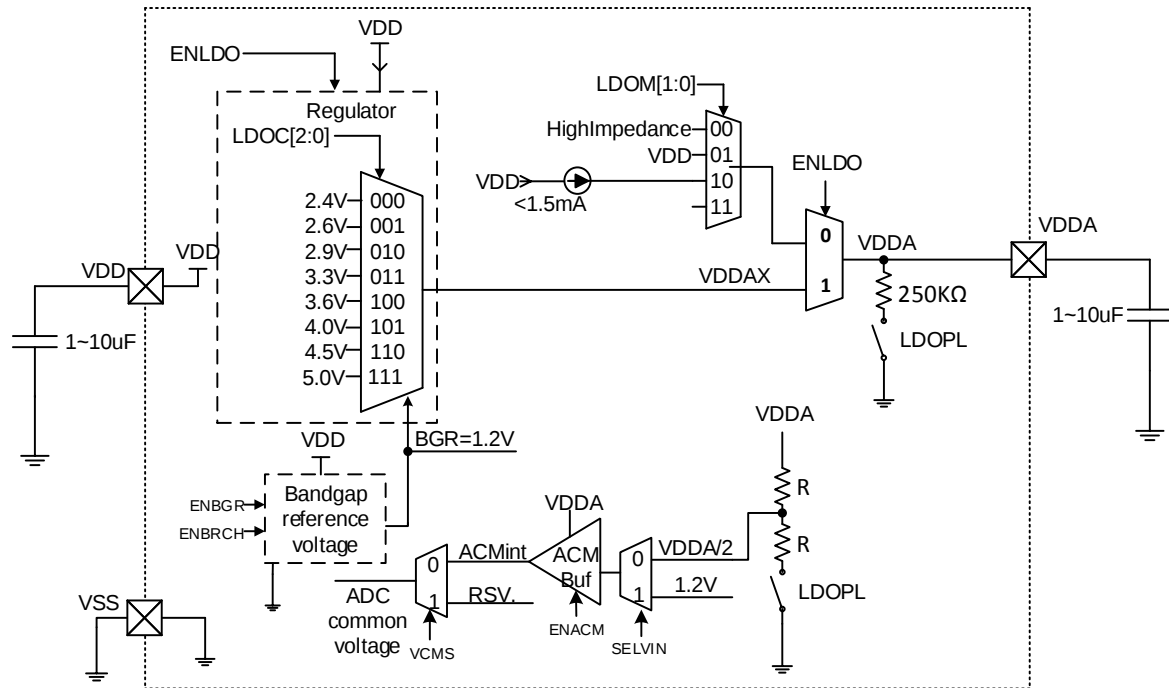


Figure 4-7 Power System

4.7. ADC Network

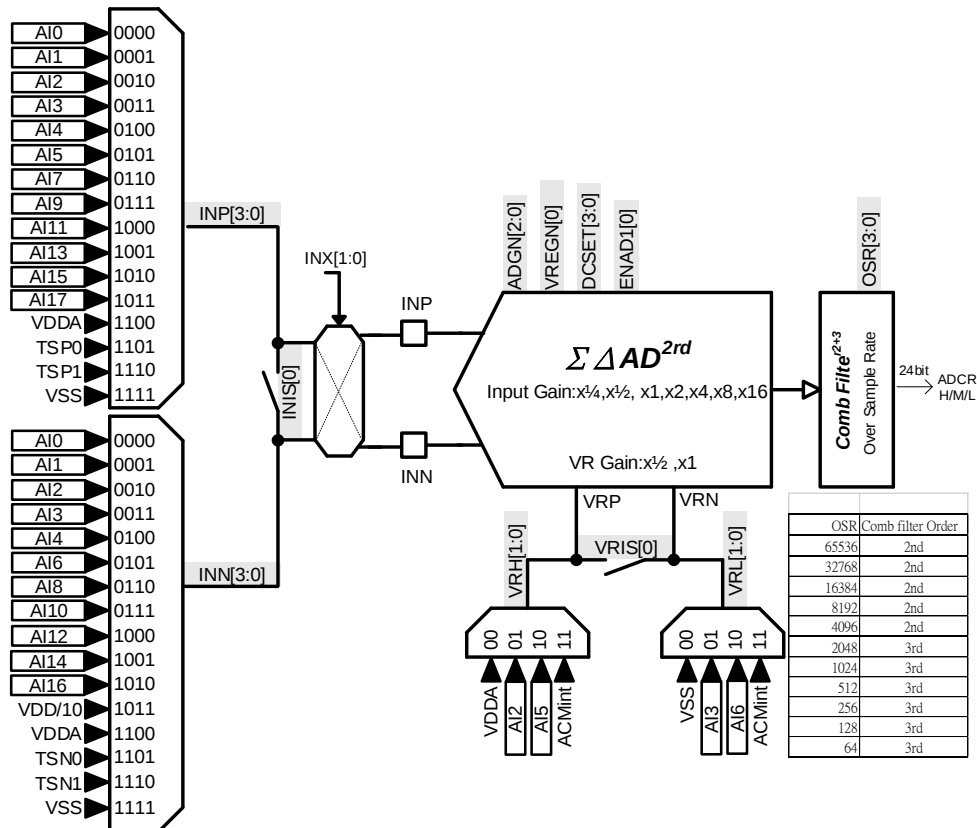


Figure 4-8 ADC Network

4.8. Comparator Network

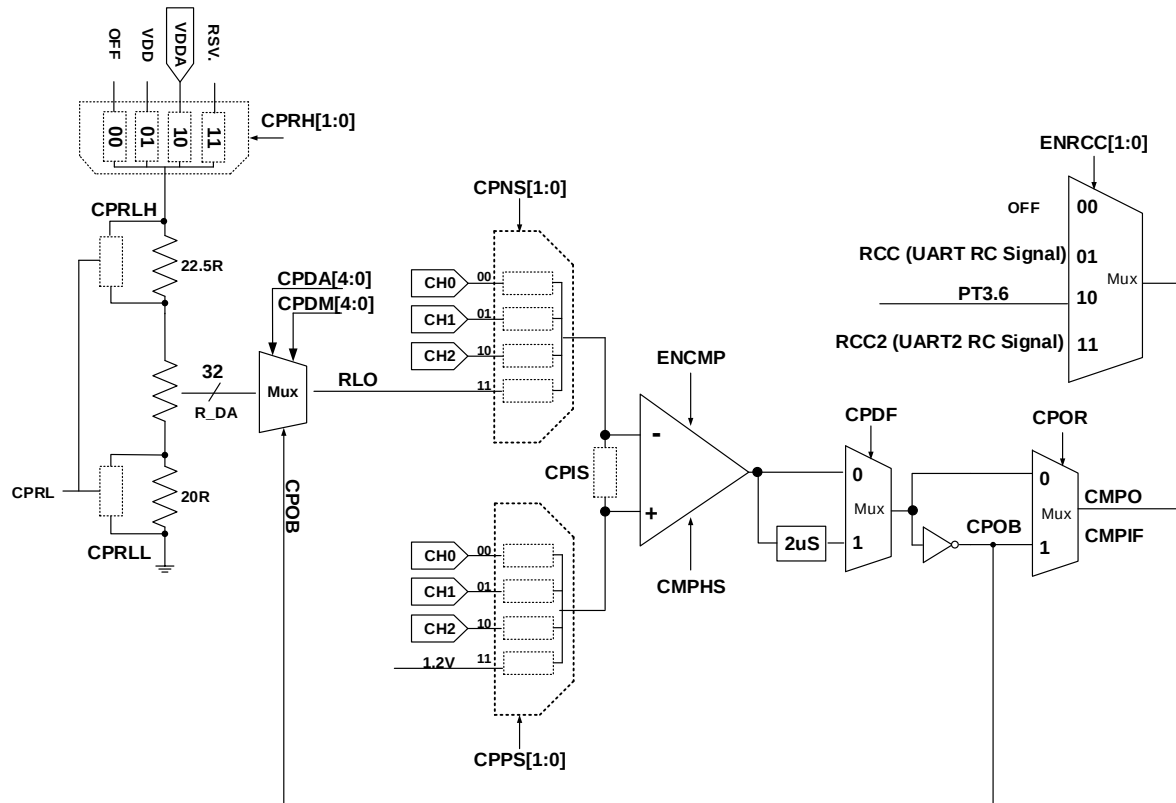


Figure 4-9 Comparator Network

4.9. Watch Dog System

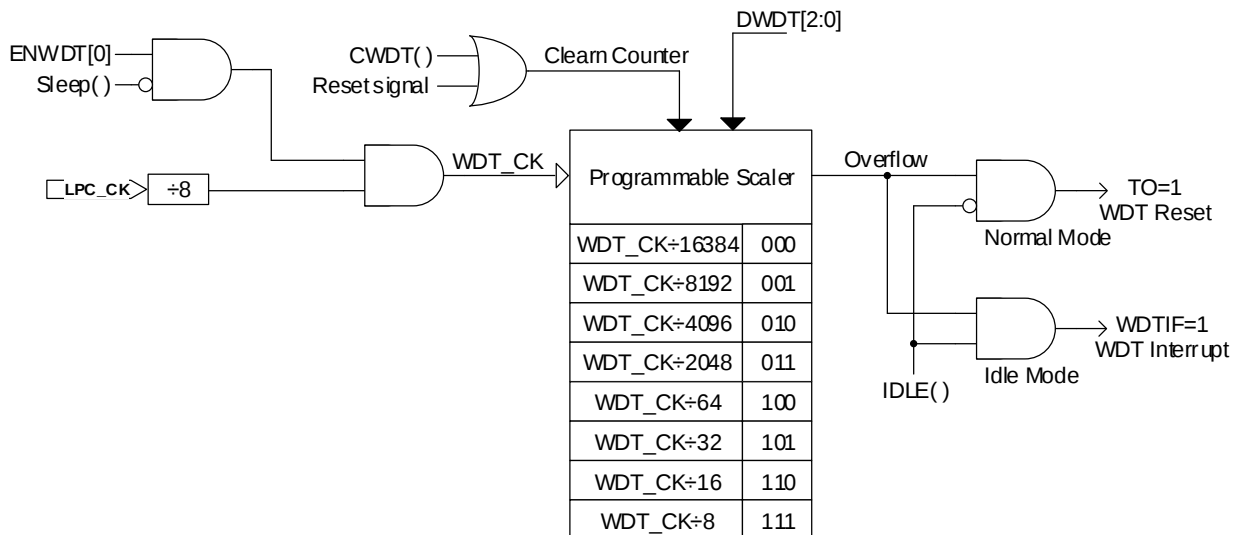


Figure 4-10 Watch Dog System

4.10. 8-bit Timer A1 System (TMA1)

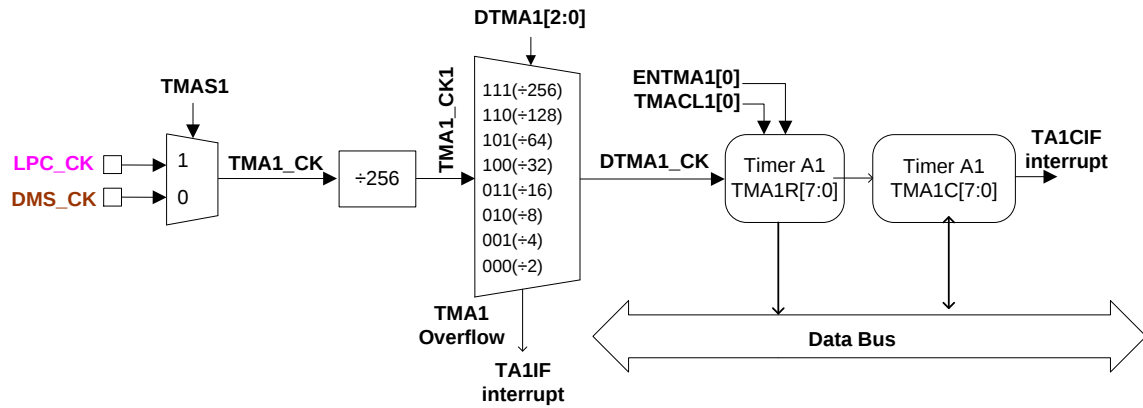


Figure 4-11 Timer A1 System

4.11. 8-bit Timer A2 System (TMA2)

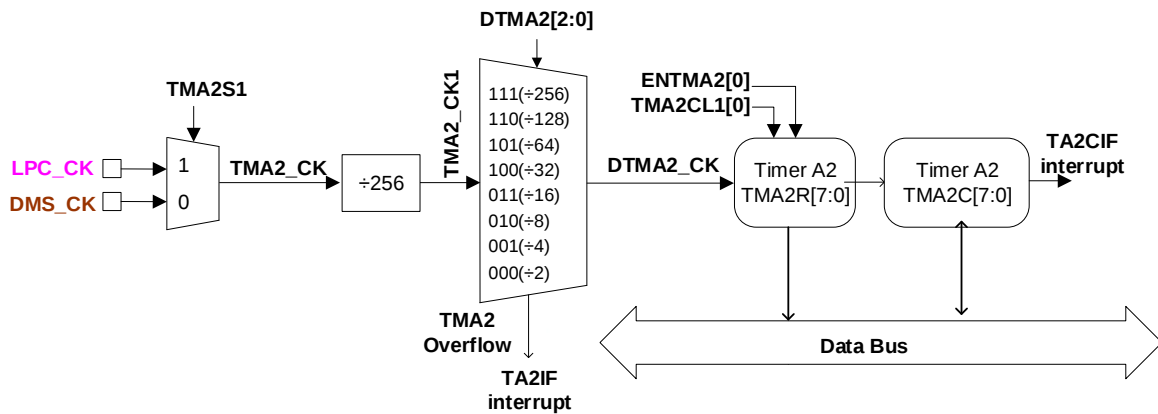


Figure 4-12 Timer A2 System

4.12. 16-bit Timer B1 System (TMB1)

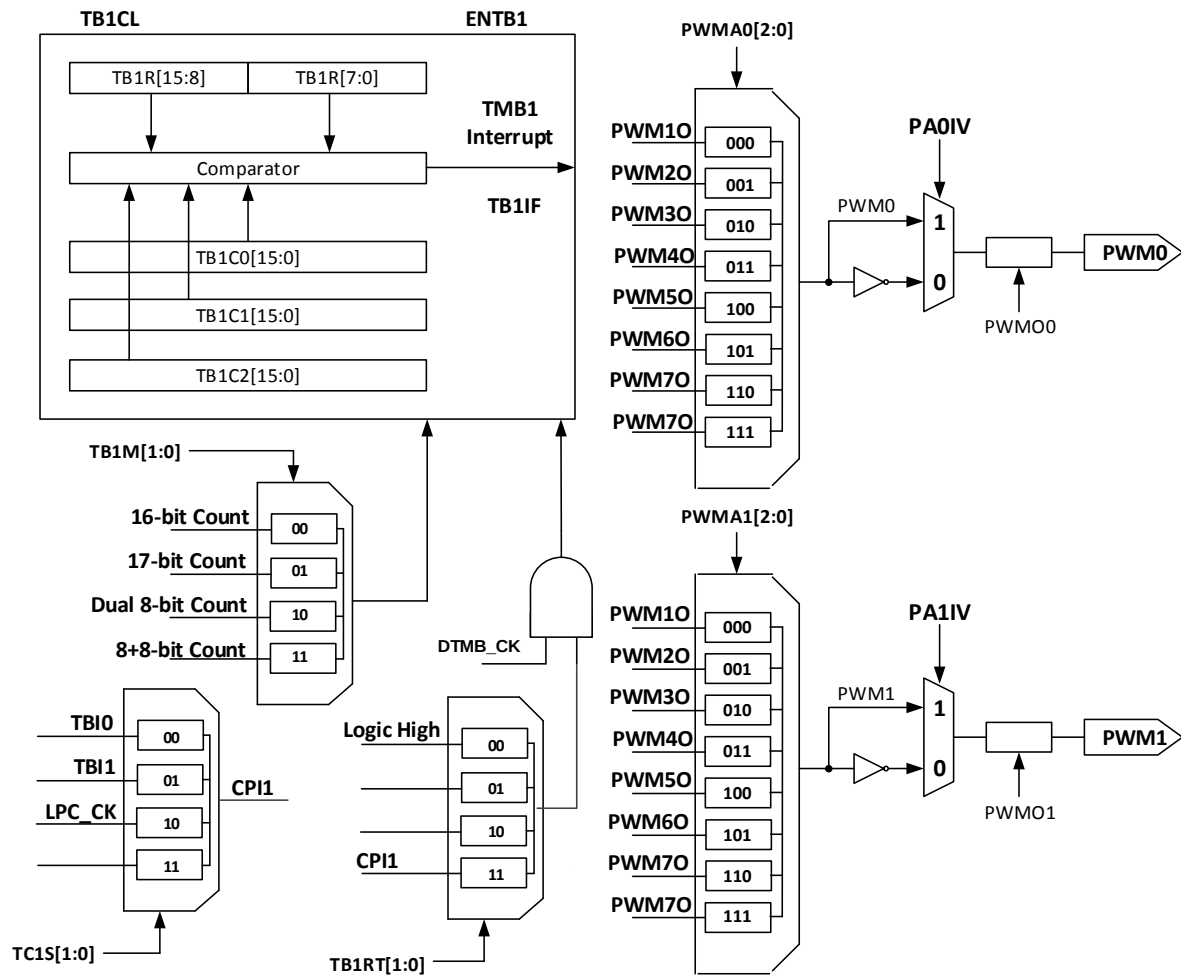


Figure 4-13 Timer B1 System

4.13. 16-bit Timer B2 System (TMB2)

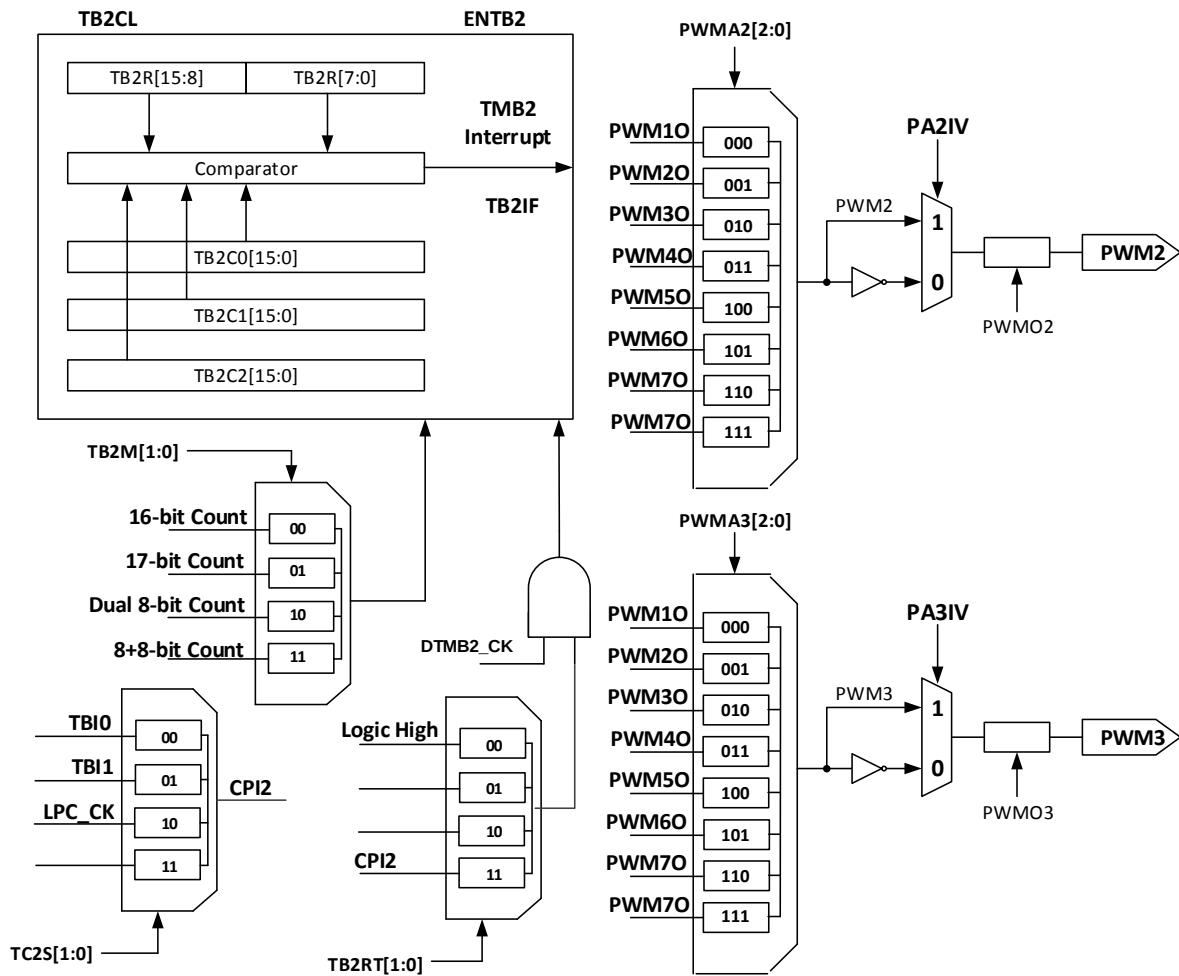


Figure 4-14 Timer B2 System

4.14. Timer C1 (TMC1)

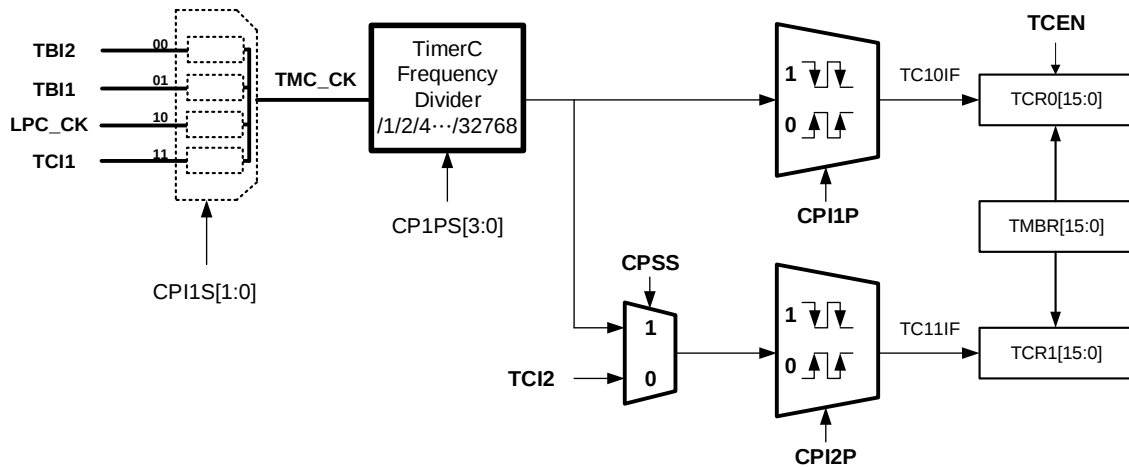


Figure 4-15 Timer C1 System

4.15. Timer C2 (TMC2)

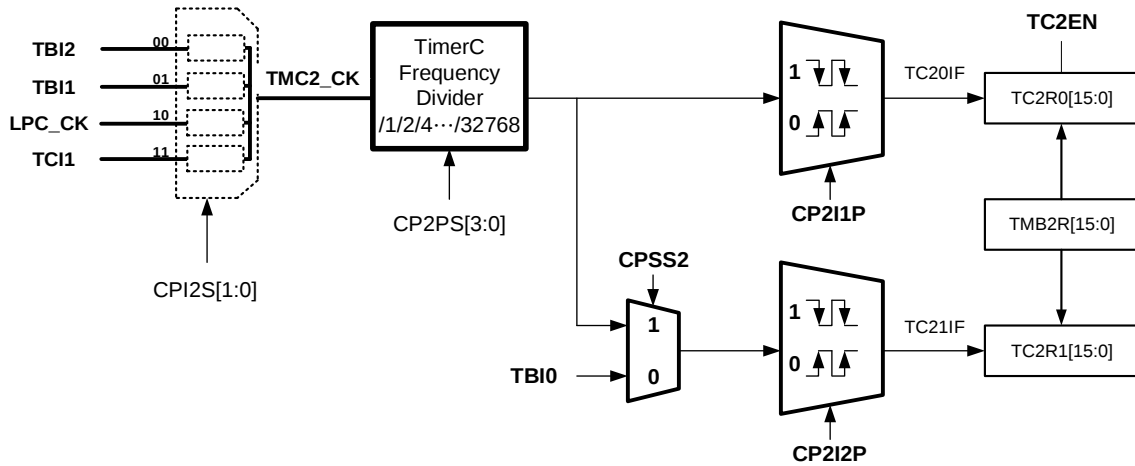


Figure 4-16 Timer C2 System

4.16. I²C and I²C2

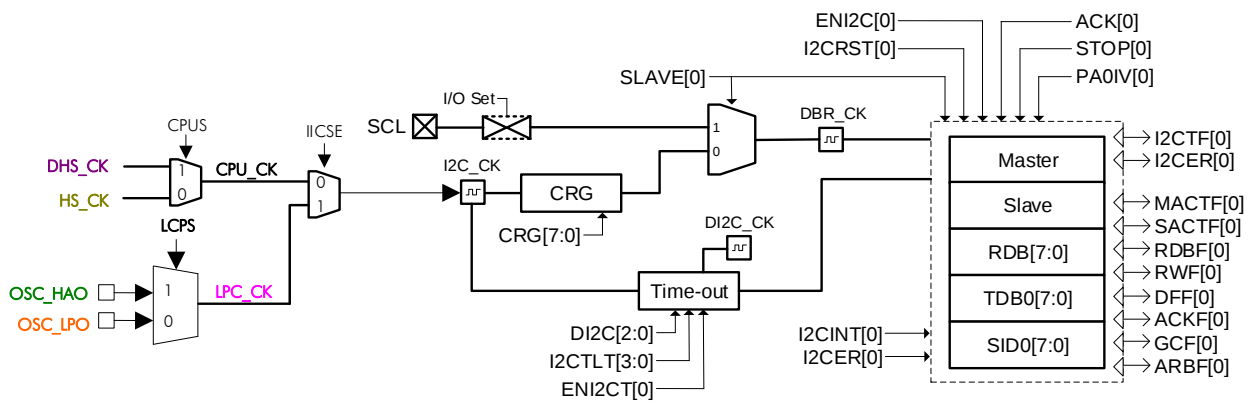


Figure 4-17 I²CBlock Diagram

4.17. EUART and EUART2

EUART TRANSMIT BLOCK DIAGRAM

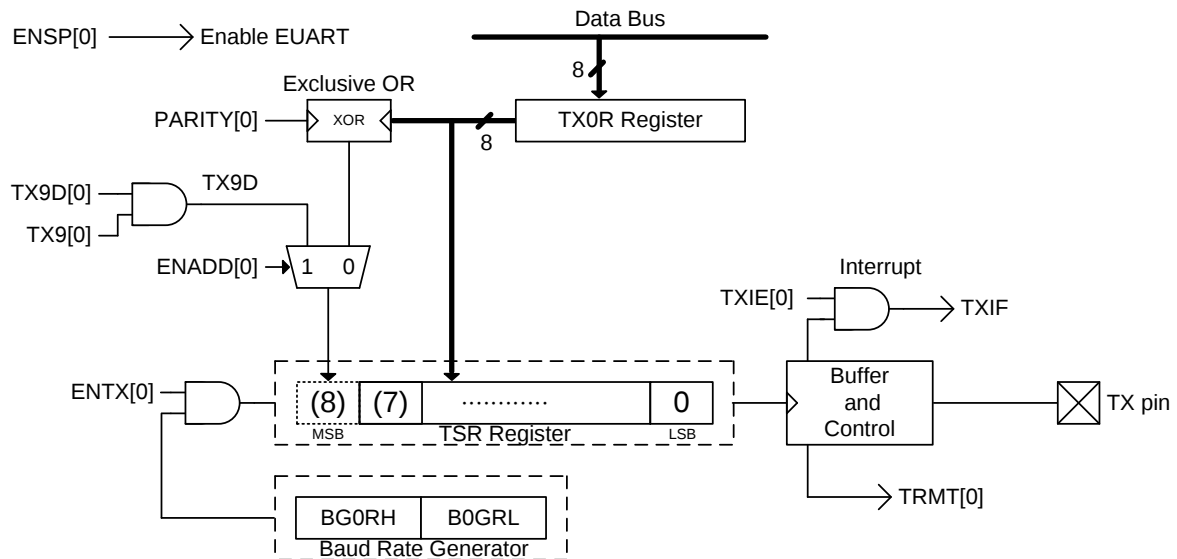
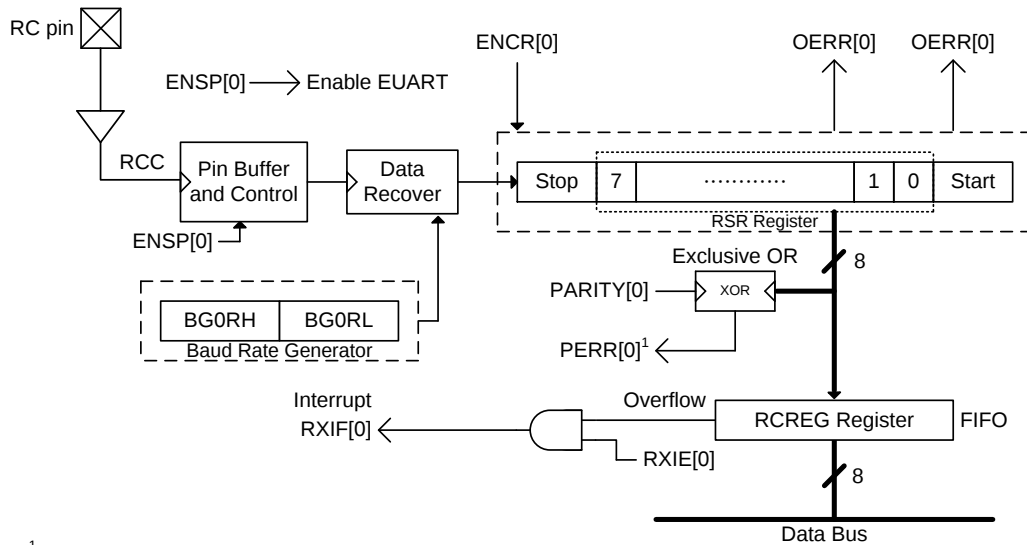


Figure 4-18 EUART Transmit Block Diagram

EUART 8-BITS RECEIVE BLOCK DIAGRAM



¹Don't care PERR[0] state of 8-bits receive mode

Figure 4-19 EUART 8-bits Receive Block Diagram

4.18. SPI

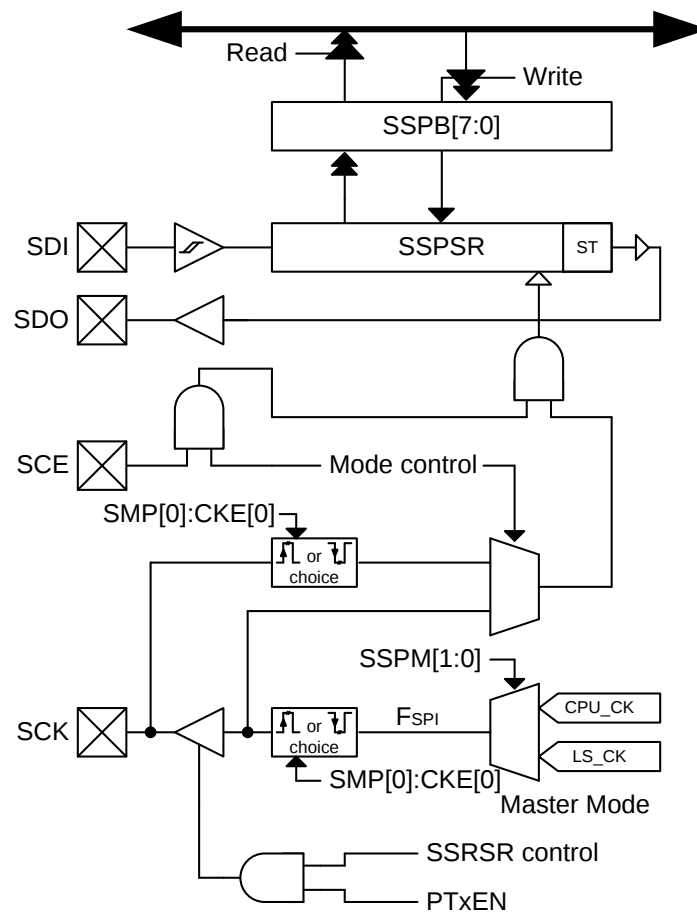


Figure 4-20 SPI Block Diagram

5. Register List

"r":no use,"w":read/write,"w":write,"r":read,"r0":only read 0,"r1":only read 1,"w0":only write 0,"w1":only write 1 "\$":for event status,"x":unimplemented bit,"x":unknown,"u":unchanged,"d":depends on condition												
Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	ARST	IRST	R/W
000h	INDF0	Contents of FSR0 to address data memoryvalue of FSR0 not changed								xxxx xxxx	uuuu uuuu	***** r r r
001h	POINC0	Contents of FSR0 to address data memoryvalue of FSR0 post-incremented								xxxx xxxx	uuuu uuuu	***** r r r
002h	PODEC0	Contents of FSR0 to address data memoryvalue of FSR0 post-decremented								xxxx xxxx	uuuu uuuu	***** r r r
003h	PRINC0	Contents of FSR0 to address data memoryvalue of FSR0 pre-incremented								xxxx xxxx	uuuu uuuu	***** r r r
004h	PLUSW0	Contents of FSR0 to address data memoryvalue of FSR0 offset by W								xxxx xxxx	uuuu uuuu	***** r r r
005h	INDF1	Contents of FSR1 to address data memoryvalue of FSR1 not changed								xxxx xxxx	uuuu uuuu	***** r r r
006h	POINC1	Contents of FSR1 to address data memoryvalue of FSR1 post-incremented								xxxx xxxx	uuuu uuuu	***** r r r
007h	PODEC1	Contents of FSR1 to address data memoryvalue of FSR1 post-decremented								xxxx xxxx	uuuu uuuu	***** r r r
008h	PRINC1	Contents of FSR1 to address data memoryvalue of FSR1 pre-incremented								xxxx xxxx	uuuu uuuu	***** r r r
009h	PLUSW1	Contents of FSR1 to address data memoryvalue of FSR1 offset by W								xxxx xxxx	uuuu uuuu	***** r r r
00Ah	INDF2	Contents of FSR2 to address data memoryvalue of FSR2 not changed								xxxx xxxx	uuuu uuuu	***** r r r
00Bh	POINC2	Contents of FSR2 to address data memoryvalue of FSR2 post-incremented								xxxx xxxx	uuuu uuuu	***** r r r
00Ch	PODEC2	Contents of FSR2 to address data memoryvalue of FSR2 post-decremented								xxxx xxxx	uuuu uuuu	***** r r r
00Dh	PRINC2	Contents of FSR2 to address data memoryvalue of FSR2 pre-incremented								xxxx xxxx	uuuu uuuu	***** r r r
00Eh	PLUSW2	Contents of FSR2 to address data memoryvalue of FSR2 offset by W								xxxx xxxx	uuuu uuuu	***** r r r
00Fh	FSR0H	-	-	-	-	-	-	-	FSR0[9:8]	xx	uu	-,-,-,-,-,-,*
010h	FSR0L	Indirect Data Memory Address Pointer 0 Low Byte,FSR0[7:0]								xxxx xxxx	uuuu uuuu	***** r r r
011h	FSR1H	-	-	-	-	-	-	-	FSR1[9:8]	xx	uu	-,-,-,-,-,-,*
012h	FSR1L	Indirect Data Memory Address Pointer 0 Low Byte,FSR1[7:0]								xxxx xxxx	uuuu uuuu	***** r r r
013h	FSR2H	-	-	-	-	-	-	-	FSR2[9:8]	xx	uu	-,-,-,-,-,-,*
014h	FSR2L	Indirect Data Memory Address Pointer 0 Low Byte,FSR2[7:0]								xxxx xxxx	uuuu uuuu	***** r r r
015h	TOSU	-	-	-	-	-	-	-	-	xxxx xxxx	uuuu uuuu	***** r r r
016h	TOSH	-	-	-	TOS[12:8]				-	...X xxxx	...u uuuu	-,-,-,-,-,-,*
017h	TOSL	Top-of-Stack Low Byte (TOS<7:0>)								xxxx xxxx	uuuu uuuu	***** r r r
018h	SKCN	SKFL	SKUN	SKOV	-	SKPRT[3:0]			-	000. 0000	u\$. \$\$\$\$	rw 0,rw 0,rw 0,***** r r r
019h	PCLATU	-	-	-	-	-	-	-	-	xxxx xxxx	uuuu uuuu	***** r r r
01Ah	PCLATH	-	-	-	PC[12:8]				-	...0 0000	...0 0000	-,-,-,-,-,-,*
01Bh	PCLATL	PC Low Byte for PC<7:0>								0000 0000	0000 0000	***** r r r
01Ch	TBLPTRU	-	-	-	-	-	-	-	-	xxxx xxxx	uuuu uuuu	***** r r r
01Dh	TBLPTRH	-	-	-	TBLPTR[12:8]				-	...X xxxx	...u uuuu	-,-,-,-,-,-,*
01Eh	TBLPTRL	Program Memory Table Pointer Low Byte (TBLPTR<7:0>)								xxxx xxxx	uuuu uuuu	***** r r r
01Fh	TBLDH	Program Memory Table Latch High Byte								xxxx xxxx	uuuu uuuu	***** r r r
020h	TBLDL	Program Memory Table Latch Low Byte								xxxx xxxx	uuuu uuuu	***** r r r
021h	PRODH	Product Register of Multiply High Byte								xxxx xxxx	uuuu uuuu	***** r r r
022h	PRODL	Product Register of Multiply Low Byte								xxxx xxxx	uuuu uuuu	***** r r r
023h	INT0	GIE	TA1CIE	ADIE	WDTIE	TB1IE	-	E1IE	E0IE	0000 0.00	0uuu uuuu	***** r r r
024h	INT1	TA1IE	SPIE	TXIE	RCIE	I2CERIE	I2CIE	E3IE	E2IE	0000 0000	uuuu uuuu	***** r r r
025h	INT2	TA2IE	TA2CIE	TC11IE	TC10IE	-	CMPIE	TB2IE	BOR2IE	0000 .000	uuuu uuuu	***** r r r
026h	INTF0	-	TA1CIF	ADIF	WDTIF	TB1IF	-	E1IF	E0IF	.000 0.00	.uuu uuuu	***** r r r
027h	INTF1	TA1IF	SPIF	TXIF	RCIF	I2CERIF	I2CIF	E3IF	E2IF	0000 0000	uuuu uuuu	***** r,r,r,r,r
028h	INTF2	TA2IF	TA2CIF	TC1IF	TC0IF	-	CMPIF	TB2IF	BOR2IF	0000 .000	uuuu uuuu	***** r r r
029h	WREG	Working Register								xxxx xxxx	uuuu uuuu	***** r r r
02Ah	BSRCN	-	-	-	-	-	-	-	BSR[0]	xx	uu	-,-,-,-,-,-,*
02Bh	MSTAT	-	-	-	C	DC	N	OV	Z	...X xxxx	...u uuuu	-,-,-,-,-,-,*
02Ch	PSTAT	BOR	PD	TO	IDL	RST	SKERR	BOR2LV	GCRstIF	\$000 \$000	uu\$u u\$uu	rw0,rw0,rw0,rw0,rw0,rw0
02Eh	INT3	-	-	TX2IE	RC2IE	TC21IE	TC20IE	I2CER2IE	I2C2IE	00 0000	uuuu uuuu	***** r r r
02Fh	INTF3	-	GC2RstIF	TX2IF	RC2IF	TC21IF	TC20IF	I2CER2IF	I2C2IF	.000 0000	uuuu uuuu	*rw 0,*,*,*,*,*,*,*
030h	PWRCN	ENBGR	LDOC[2:0]			LDM[1:0]		ENLDO	CSFON	1000 0000	uuuu uu0u	***** r r r
031h	OSCCN0	OSCS[1:0]		DHS[1:0]		DMS[2:0]		CUPS		0000 0000	uuuu uuuu	***** r r r
032h	OSCCN1	CCOPT	LCPS	DADC[1:0]		DTMB[1:0]		TMBS		0000 000.	uuuu uu..	***** r r r
033h	OSCCN2	IDLEM1	IDLEM0	ENXT	XTS[1:0]		HAOM[1:0]		ENHAO	0000 0001	uuuu uu01	***** r r r
034h	OSCCN3	-	-	-	DTMB2[1:0]			TMB2S		 000.	 uu..	***** r r r
035h	CSFCN0	SKRST	HAOTR[6:0]						-	.1..		-,-,-,-,-,-,*
036h	CSFCN1	MCLR	-	ENINXCH	BOR_TH[2:0]		BORS		ENBOR2	0.00 0011	0.uu uuuu	*-***** r r r
037h	CSFCN2	-	-	-	-	-	-	-	-	00..	00uu uuuu	***** r r r

Table 5-1 Register List

HY17M26

8-bit RISC-like Mixed Signal Microcontrollers with
Embedded High Resolution $\Sigma\Delta$ ADC for bridge sensor application



"r"no use,"w"read/write,"w"write,"r"read,"r0"only read 0,"r1"only read 1,"w0"only write 0,"w1"only write 1 "\$"for event status,"u"unimplemented bit,"x"unknown,"u"unchanged,"d"depends on condition												
Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	ARST	IRST	R/W
038h	WDTCN	ENBZ	BZS	BZ[1:0]		ENWDT	DWDT[2:0]			0000 0000	uuuu \$000	-,*** rw 1***
039h	AD1H	ADC1 conversion high byte data register								0000 0000	uuuu uuuu	r,r,r,r,r,r,r
03Ah	AD1M	ADC1 conversion middle byte data register								0000 0000	uuuu uuuu	r,r,r,r,r,r,r
03Bh	AD1L	ADC1 conversion low byte data register								0000 0000	uuuu uuuu	r,r,r,r,r,r,r
03Ch	AD1HH	ADC1 conversion high byte data register								0000 0000	uuuu uuuu	*****
03Dh	AD1MM	ADC1 conversion middle byte data register								0000 0000	uuuu uuuu	*****
03Eh	AD1LL	ADC1 conversion low byte data register								0000 0000	uuuu uuuu	*****
03Fh	AD1CN0	ENAD1	-		OSR[3:0]				CMFR	0000 0000	uuuu uuuu	*****
040h	AD1CN1	-	-	VREGN	-	-	ADGN[2:0]			000. .000	uuuu uuuu	*****
041h	AD1CN2		-	SELVIN	DCSET[3:0]					..00 0000	uuuu uuuu	*****
042h	AD1CN3	INP[3:0]			INN[3:0]					0000 0000	uuuu uuuu	*****
043h	AD1CN4	VRH[1:0]		VRL[1:0]		INX[1:0]		VRIS	INIS	0000 0000	uuuu uuuu	*****
044h	AD1CN5	ENACM	-	VCMS	LDOPL	-	-	ENTPS	TPSCH	0.00 .000	uuuu uuuu	*****
045h	LVDCN	DAFM	ENCH	-	-	-	-	-	-	00..	uu..	*****
046h	MCCN0	ENRCC[1:0]		CMPO	CPIS	CPOR	CPDF	CMPHS	ENCMP	0000 0000	uuuu uuuu	*,r,*****
047h	MCCN1	CPRL	VRSEL	CPRH[1:0]		CPPS[1:0]		CPNS[1:0]		0000 0000	uuuu uuuu	*****
048h	MCCN2			CPDA[4:0]						0000 0000	uuuu uuuu	*****
049h	MCCN3			CPDM[4:0]						0000 0000	uuuu uuuu	*****
04Ah	-	-	-	-	-	-	-	-	-	0000 .000	uuuu .uuu	****,***
04Bh	TMA1CN	ENTMA1	TMACL1	TMAS1	DTMA1[2:0]			-		0000 0000	u0uu uuuu	*,rw 1,*****
04Ch	TMA1R	TMA1 counter Register								0000 0000	uuuu uuuu	rw0,rw0,rw0,rw0,rw0,rw0,rw0
04Dh	TMA1C	TMA1C counter Register								0000 0000	uuuu uuuu	rw0,rw0,rw0,rw0,rw0,rw0,rw0
04Eh	TMA2CN	ENTMA2	TMA2CL1	TMAS2	DTMA2[2:0]			-	-	0000 0000	u0uu uuuu	*,rw 1,*****
04Fh	TMA2R	TMA2 counter Register								0000 0000	uuuu uuuu	rw0,rw0,rw0,rw0,rw0,rw0,rw0
050h	TMA2C	TMA2C counter Register								0000 0000	uuuu uuuu	rw0,rw0,rw0,rw0,rw0,rw0,rw0
051h	TB1Flag	-	PWM7A	PWM6A	PWM5A	PWM4A	PWM3A	PWM2A	PWM1A	..00 0000	..uu uuuu	-,r,r,r,r,r,r
052h	TB1CN0	ENTB1	TB1M[1:0]		TB1RT[1:0]		TB1CL	PWMO1	PWMO0	0000 0000	uuuu u0uu	****,rw 1,**
053h	TB1CN1	PA1IV	PWMA1[2:0]			PA0IV	PWMA0[2:0]			0000 0000	uuuu uuuu	*****
054h	TB1RH	TimerB1 counter Register [15:8]								xxxx xxxx	uuuu uuuu	r,r,r,r,r,r,r
055h	TB1RL	TimerB1 counter Register [7:0]								xxxx xxxx	uuuu uuuu	r,r,r,r,r,r,r
056h	TB1C0H	TimerB1 counter Condition Register [15:8]								xxxx xxxx	uuuu uuuu	*****
057h	TB1C0L	TimerB1 counter Condition Register [7:0]								xxxx xxxx	uuuu uuuu	*****
058h	TB1C1H	TimerB1 counter Condition Register [15:8]								xxxx xxxx	uuuu uuuu	*****
059h	TB1C1L	TimerB1 counter Condition Register [7:0]								xxxx xxxx	uuuu uuuu	*****
05Ah	TB1C2H	TimerB1 counter Condition Register [15:8]								xxxx xxxx	uuuu uuuu	*****
05Bh	TB1C2L	TimerB1 counter Condition Register [7:0]								xxxx xxxx	uuuu uuuu	*****
05Ch	TC1CN0		TC1S[1:0]				CP1P	CP1P	TCEN	0000 0000	uuuu uuuu	uuuu uuuu
05Dh	TC1CN1	-	CPSS	CP1S[1:0]		CP1PS[3:0]				0000 0000	uuuu uuuu	uuuu uuuu
05Eh	TC1R0H	Timer C1 Capture 0 High Byte Data Register								xxxx xxxx	uuuu uuuu	uuuu uuuu
05Fh	TC1R0L	Timer C1 Capture 0 Low Byte Data Register								xxxx xxxx	uuuu uuuu	uuuu uuuu
060h	TC1R1H	Timer C1 Capture 1 High Byte Data Register								xxxx xxxx	uuuu uuuu	uuuu uuuu
061h	TC1R1L	Timer C1 Capture 1 Low Byte Data Register								xxxx xxxx	uuuu uuuu	uuuu uuuu
062h	TB2Flag	-	PWM7A	PWM6A	PWM5A	PWM4A	PWM3A	PWM2A	PWM1A	..00 0000	..uu uuuu	-,r,r,r,r,r,r
063h	TB2CN0	ENTB2	TB2M[1:0]		TB2RT[1:0]		TB2CL	PWMO3	PWMO2	0000 0000	uuuu u0uu	****,rw 1,**
064h	TB2CN1	PA3IV	PWMA3[2:0]			PA2IV	PWMA2[2:0]			0000 0000	uuuu uuuu	*****
065h	TB2RH	TimerB2 counter Register [15:8]								xxxx xxxx	uuuu uuuu	r,r,r,r,r,r,r
066h	TB2RL	TimerB2 counter Register [7:0]								xxxx xxxx	uuuu uuuu	r,r,r,r,r,r,r
067h	TB2C0H	TimerB2 counter Condition Register [15:8]								xxxx xxxx	uuuu uuuu	*****
068h	TB2C0L	TimerB2 counter Condition Register [7:0]								xxxx xxxx	uuuu uuuu	*****
069h	TB2C1H	TimerB2 counter Condition Register [15:8]								xxxx xxxx	uuuu uuuu	*****
06Ah	TB2C1L	TimerB2 counter Condition Register [7:0]								xxxx xxxx	uuuu uuuu	*****
06Bh	TB2C2H	TimerB2 counter Condition Register [15:8]								xxxx xxxx	uuuu uuuu	*****
06Ch	TB2C2L	TimerB2 counter Condition Register [7:0]								xxxx xxxx	uuuu uuuu	*****
06Dh	TC2CN0		TC2S[1:0]				CP21P	CP21P	TC2EN	0000 0000	uuuu uuuu	uuuu uuuu
06Eh	TC2CN1	-	CPSS2	CP2S[1:0]		CP2PS[3:0]				0000 0000	uuuu uuuu	uuuu uuuu
06Fh	TC2R0H	Timer C2 Capture 0 High Byte Data Register								xxxx xxxx	uuuu uuuu	uuuu uuuu
070h	TC2R0L	Timer C2 Capture 0 Low Byte Data Register								xxxx xxxx	uuuu uuuu	uuuu uuuu
071h	TC2R1H	Timer C2 Capture 1 High Byte Data Register								xxxx xxxx	uuuu uuuu	uuuu uuuu
072h	TC2R1L	Timer C2 Capture 1 Low Byte Data Register								xxxx xxxx	uuuu uuuu	uuuu uuuu

Table 5-2 Register List

8-bit RISC-like Mixed Signal Microcontrollers with Embedded High Resolution $\Sigma\Delta$ ADC for bridge sensor application

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HY17M26

8-bit RISC-like Mixed Signal Microcontrollers with
Embedded High Resolution $\Sigma\Delta$ ADC for bridge sensor application



"r"no use,"w"read/write,"w"write,"r"read,"r0"only read 0,"r1"only read 1,"w0"only write 0,"w1"only write 1 "\$"for event status,"x"unimplemented bit,"x"unknown,"u"unchanged,"d"depends on condition												
Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	ARST	IRST	R/W
1B7h	CFG2	IICSE	-	-	-	-	GCRst	ENI2CT	ENI2C	0..000	u..uuu	*-,-,-*** 1 1 1 1 1 1
1B8h	ACT2	SLAVE	-	-	I2CER	START	STOP	I2CINT	ACK	0.0 0000	u..u uuuu	***** 1 1 1 1 1 1
1B9h	STA2	MACTF	SACTF	RDBF	RWF	DF	ACKF	GCF	ARBF	0001 0000	uuuu uuuu	***** 1 1 1 1 1 1
1BAh	CRG2	CRG[7:0]								0000 0000	uuuu uuuu	***** 1 1 1 1 1 1
1BBh	TOC2	I2CTF	DI2C[2:0]			I2CTL[3:0]			0000 0000	uuuu uuuu	***** 1 1 1 1 1 1	
1BCh	RDB2	RDB2[7:1]							RDB2[0]	xxxx xxxx	uuuu uuuu	***** 1 1 1 1 1 1
1BDh	TDB2	TDB2[7:1]							TDB2[0]	xxxx xxxx	uuuu uuuu	***** 1 1 1 1 1 1
1BEh	SID2	SID2[7:1],The corresponding address of the 7-bit mode							SID0V[0]	0000 0000	uuuu uuuu	***** 1 1 1 1 1 1
1BFh	SSPCN0	ENSSP	CKP	CKE	SMP	-	-	SSPM[1:0]		0000 ..00	uuuu ..uu	****-*** 1 1 1 1 1 1
1C0h	SSPSTA0	SSPBY	SSPOV	-	-	-	-	-	BF	00.. ..0	uu.. ..u	*-,-,-*** 1 1 1 1 1 1
1C1h	SSPBUF0	SSP Receive/Transmit Buffer Register								xxxx xxxx	uuuu uuuu	***** 1 1 1 1 1 1
1C2h	UR2CN	ENSP	ENTX	TX9	TX9D	PARITY	-	-	WUE	0000 0..0	uuuu u..u	*****- 1 1 1 1 1 1
1C3h	UR2STA	-	RC9D	PERR	FERR	OERR	RCIDL	TRMT	ABDOVF	.000 0010	.uuu uuuu	-,f,f,f,f,f,f,fw 0 1 1 1 1 1 1
1C4h	BA2CN	UART2SE	-	-	-	ENCR	RC9	ENADD	ENABD	0... 0000	u... uuuu	*-,-,-*** 1 1 1 1 1 1
1C5h	BG2RH	-	-	-	UART2 Baud Rate Register High Byte					...X xxxx	...u uuuu	-,-,-,-*** 1 1 1 1 1 1
1C6h	BG2RL	UART2 Baud Rate Generator Register Low Byte								xxxx xxxx	uuuu uuuu	***** 1 1 1 1 1 1
1C7h	TX2R	UART2 Transmit Register								xxxx xxxx	uuuu uuuu	***** 1 1 1 1 1 1
1C8h	RC2REG	UART2 Receive Register								xxxx xxxx	uuuu uuuu	f,f,f,f,f,f,f,f 1 1 1 1 1 1
1C9h	FWRST	FWRST data register[7:0]								0000 0000	uuuu uuuu	***** 1 1 1 1 1 1
1CAh	-	-	-	-	-	-	-	-	-	0000 0000	0000 0000	f,f,f,f,f,f,f,f 1 1 1 1 1 1
1CBh	-	-								0000 0000	0000 0000	***** 1 1 1 1 1 1
1CCh	-	-								0000 0000	0000 0000	***** 1 1 1 1 1 1
1CDh	-								-	xxxx xxxx	xxxx xxxx	f,f,f,f,f,f,f,f 1 1 1 1 1 1
1CEh	-	-								xxxx xxxx	xxxx xxxx	f,f,f,f,f,f,f,f 1 1 1 1 1 1
1CFh	-								-	xxxx xxxx	xxxx xxxx	f,f,f,f,f,f,f,f 1 1 1 1 1 1
1D0h	-	-								0000 0000	0000 0000	***** 1 1 1 1 1 1
080h ~ 0FFh		SRAM as 128Byte								uuuu uuuu	uuuu uuuu	***** 1 1 1 1 1 1
100h ~ 17Fh		SRAM as 128Byte								uuuu uuuu	uuuu uuuu	***** 1 1 1 1 1 1
200h ~ 2FFh		SRAM as 256Byte								uuuu uuuu	uuuu uuuu	***** 1 1 1 1 1 1
300h ~ 37Fh		BIE2 Data Buffer (128Byte)								uuuu uuuu	uuuu uuuu	***** 1 1 1 1 1 1

Table 5-4 Register List

6. Electrical Characteristics

Absolute Maximum Ratings :

Absolute maximum ratings over operating free-air temperature (unless otherwise noted)

Voltage applied at V_{DD} to V_{SS} -0.2 V to 6.0 V

Voltage applied to any pin -0.2 V to $V_{DD} + 0.3$ V

Diode current at any device terminal ± 2 mA

Storage temperature, -55°C to 125°C

(Operation Mode) -40°C to 85°C

Total power dissipation. 0.5w

Maximum output current sink by any I/O pin. 20mA

6.1. Recommended operating conditions

$T_A = -40^\circ\text{C} \sim 85^\circ\text{C}$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_{DD}	Supply Voltage	All digital peripherals and CPU $V_{DD} = 1.9\text{V} \sim 5.5\text{V}$, Frequency $\leq 9.6\text{MHz}$, $V_{DD} = 3.6\text{V} \sim 5.5\text{V}$, Frequency $\leq 16\text{MHz}$,	1.9		5.5	V
V_{DDA}	Supply Voltage	Analog peripherals	2.4		5.5	
V_{SS}	Supply Voltage		0		0	

6.2. Internal RC Oscillator

$T_A = 25^\circ\text{C}$, $V_{DD} = 3.0\text{V}$, unless otherwise noted

Sym.	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
HAO	High Speed Oscillator frequency, After writer Trim.	ENHAO[0]=1b, HAOM[1:0]=00b	VDD=3V/5V, T _A = 25°C	-1%	1.843	+1%	MHz
			VDD=3V/5V, T _A = -40°C ~ 85°C	-3%	1.843	+3%	
			VDD=2.2V~5.5V, T _A = 25°C	-3%	1.843	+3%	
			VDD=2.2V~5.5V, T _A = -40°C ~ 85°C	-6%	4.147	+6%	
		ENHAO[0]=1b, HAOM[1:0]=01b	VDD=3V/5V, T _A = 25°C	-1%	4.147	+1%	MHz
			VDD=3V/5V, T _A = -40°C ~ 85°C	-3%	4.147	+3%	
			VDD=2.2V~5.5V, T _A = 25°C	-3%	4.147	+3%	
			VDD=2.2V~5.5V, T _A = -40°C ~ 85°C	-6%	4.147	+6%	
		ENHAO[0]=1b, HAOM[1:0]=10b	VDD=3V/5V, T _A = 25°C	-1%	8.755	+1%	MHz
			VDD=3V/5V, T _A = -40°C ~ 85°C	-3%	8.755	+3%	
			VDD=2.2V~5.5V, T _A = 25°C	-4%	8.755	+4%	
			VDD=2.2V~5.5V, T _A = -40°C ~ 85°C	-8%	8.755	+8%	
		ENHAO[0]=1b, HAOM[1:0]=11b	VDD=3.6V/5V, T _A = 25°C	-1%	17.51	+1%	MHz
			VDD=3.6V/5V, T _A = -40°C ~ 85°C	-3%	17.51	+3%	
			VDD=3.6V~5.5V, T _A = 25°C	-2%	17.51	+2%	
			VDD=3.6V~5.5V, T _A = -40°C ~ 85°C	-5%	17.51	+5%	
LPO	Low Power Oscillator	VDD=2.2V~5.5V, T _A = 25°C		-20%	14.5	+20%	KHz

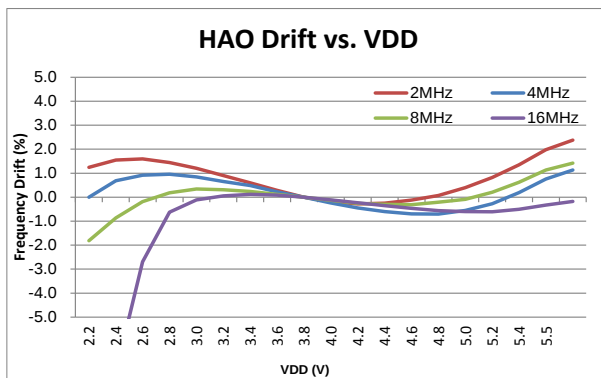


Figure 6.2-1 HAO vs. VDD

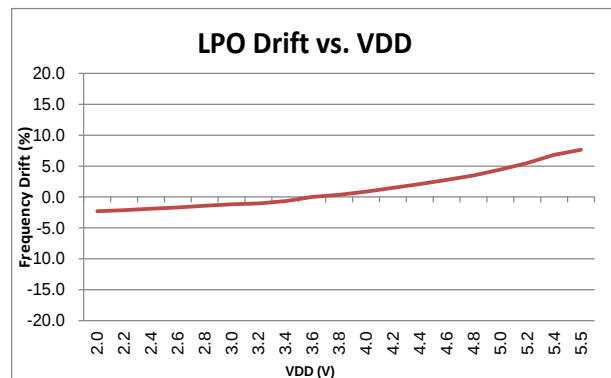


Figure 6.2-2 LPO vs. VDD

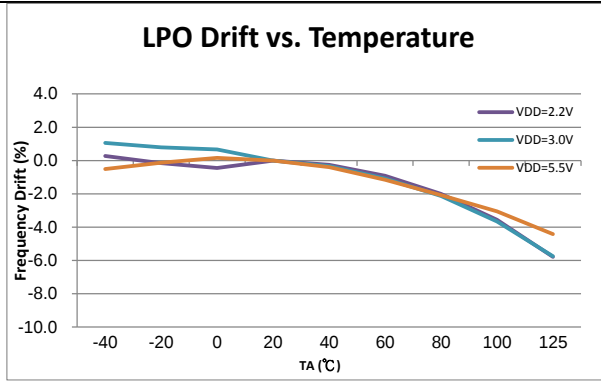


Figure 6.2-3 LPO vs. Temperature

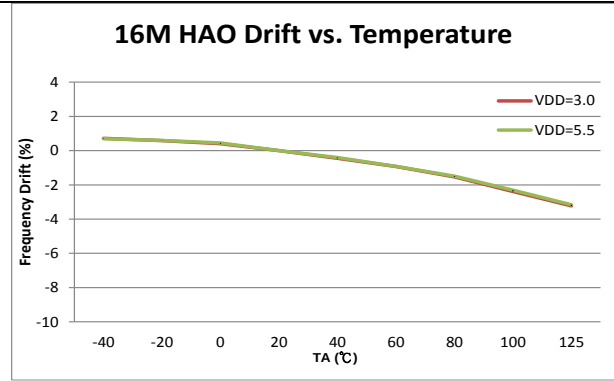


Figure 6.2-4 HAO(17.51MHz) vs. Temperature

6.3. Supply current into VDD excluding peripherals current

$T_A = 25^\circ\text{C}$, $V_{DD} = 3.0\text{V}$, $\text{OSC_LPO} = 14\text{KHz}$, BOR2 OFF , $\text{OSC_CY} = \text{off}$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{AM1}	Active mode 1	$\text{OSC_HAO} = 17.51\text{MHz}$, $\text{CPU_CK} = 17.51\text{MHz}$		1700	2500	μA
I_{AM5}	Active mode 5	$\text{OSC_HAO} = 4.147\text{MHz}$, $\text{CPU_CK} = \text{OSC_HAO}$		785	1200	μA
I_{LP1}	Low Power 1	$\text{OSC_HAO} = \text{off}$, $\text{CPU_CK} = \text{LPO}$		490	735	μA
I_{LP2}	Low Power 2	$\text{OSC_HAO} = \text{off}$, $\text{CPU_CK} = \text{LPO}$, Idle state		0.5	2	μA
I_{LP3}	Low Power 3	$\text{OSC_HAO} = \text{off}$, $\text{CPU_CK} = \text{off}$, Sleep state		0.1	1	μA

OSC_CY : External Oscillator frequency.
OSC_HAO : Internal High Accuracy Oscillator frequency.
CPU_CK : CPU core work frequency.

$T_A = 25^\circ\text{C}$, $V_{DD} = 5.5\text{V}$, $\text{OSC_LPO} = 14\text{KHz}$, BOR2 OFF , $\text{OSC_CY} = \text{off}$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{AM1}	Active mode 1	$\text{OSC_HAO} = 17.51\text{MHz}$, $\text{CPU_CK} = 17.51\text{MHz}$		2850	4200	μA
I_{AM5}	Active mode 5	$\text{OSC_HAO} = 4.147\text{MHz}$, $\text{CPU_CK} = \text{OSC_HAO}$		1100	1650	μA
I_{LP1}	Low Power 1	$\text{OSC_HAO} = \text{off}$, $\text{CPU_CK} = \text{LPO}$		510	765	μA
I_{LP2}	Low Power 2	$\text{OSC_HAO} = \text{off}$, $\text{CPU_CK} = \text{LPO}$, Idle state		1.3	4	μA
I_{LP3}	Low Power 3	$\text{OSC_HAO} = \text{off}$, $\text{CPU_CK} = \text{off}$, Sleep state		0.3	2	μA

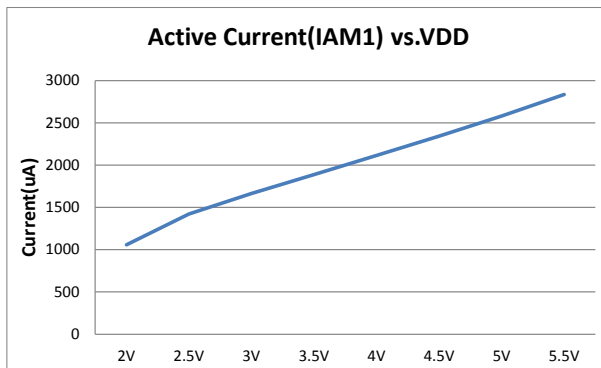


Figure 6.3-1 I_{AM1} vs. VDD

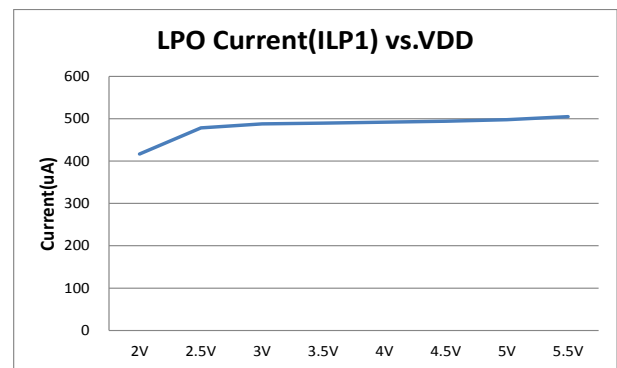


Figure 6.3-2 I_{LP1} vs. VDD

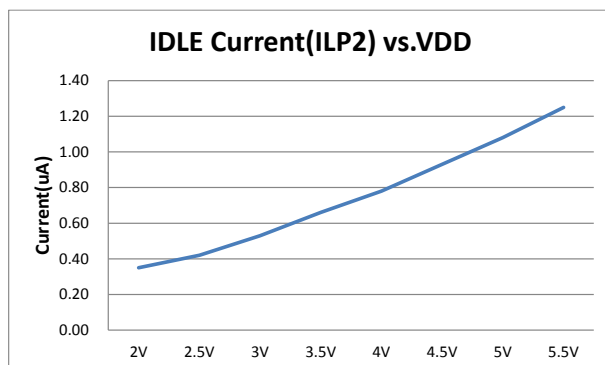


Figure 6.3-3 I_{LP2} vs. VDD

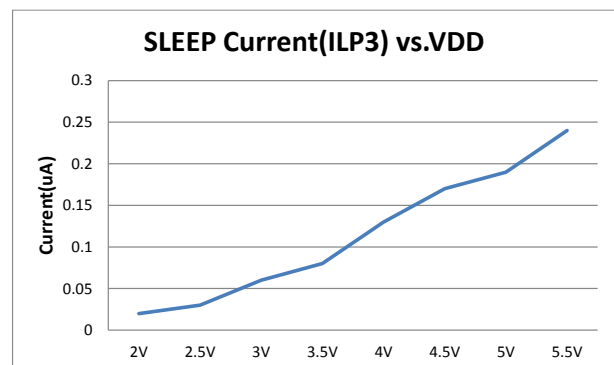


Figure 6.3-4 I_{LP3} vs. VDD

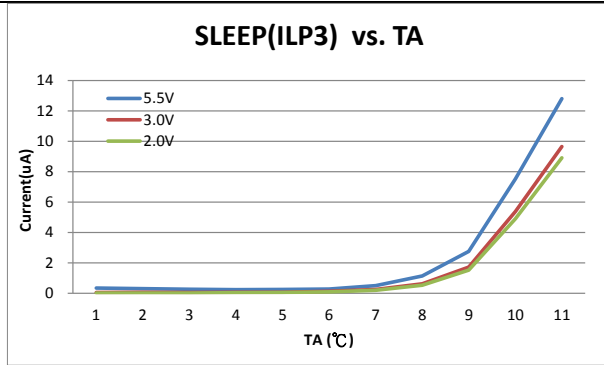


Figure 6.3-5 I_{LP3} vs. Temperature

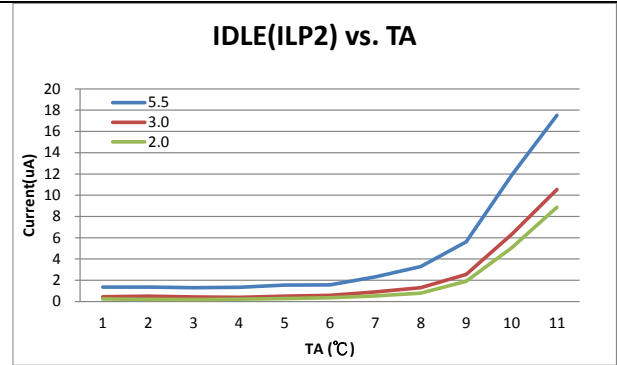


Figure 6.3-6 I_{LP2} vs. Temperature

6.4. Port 1-3

$T_A = 25^\circ\text{C}$, $V_{DD} = 3.0\text{V}$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Input voltage and Schmitt trigger and leakage current and timing						
V_{IH}	High-Level input voltage				$0.7 \cdot V_{DD}$	V
V_{IL}	Low-Level input voltage		$0.3 \cdot V_{DD}$			
V_{hys}	Input Voltage hysteresis($V_{IH} - V_{IL}$)			$0.3 \cdot V_{DD}$		V
I_{LKG}	Leakage Current				0.1	μA
R_{PU}	Port pull high resistance			60		$\text{k}\Omega$
Output voltage and current and frequency						
V_{OH}	High-level output voltage	$V_{DD}=3\text{V}, I_{OH}=-10\text{mA}$,	$V_{DD}-0.5$			V
		$V_{DD}=5\text{V}, I_{OH}=-15\text{mA}$,	$V_{DD}-0.5$			
V_{OL}	Low-level output voltage	$V_{DD}=3\text{V}, I_{OL}=10\text{mA}$			$V_{SS}+0.4$	
		$V_{DD}=5\text{V}, I_{OL}=15\text{mA}$			$V_{SS}+0.4$	

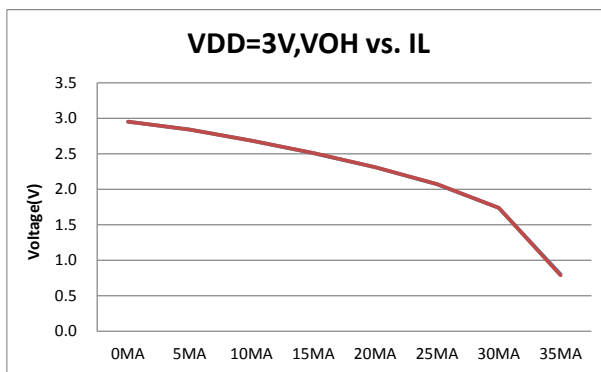


Figure 6.4-1 V_{OH} vs. I_{OH}

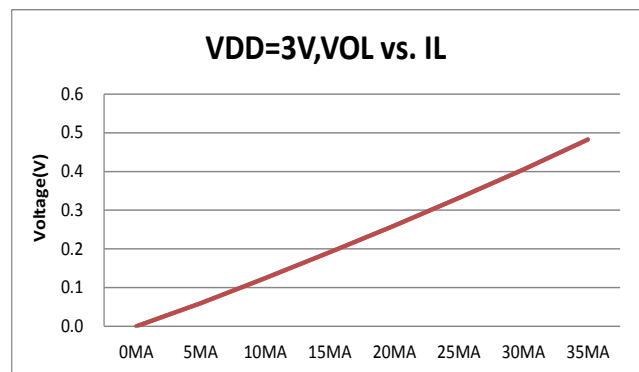


Figure 6.4-2 V_{OL} vs. I_{OL}

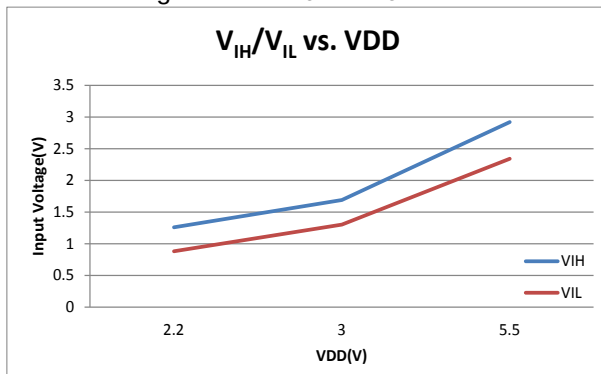


Figure 6.4-3 V_{IH}/V_{IL} vs. VDD

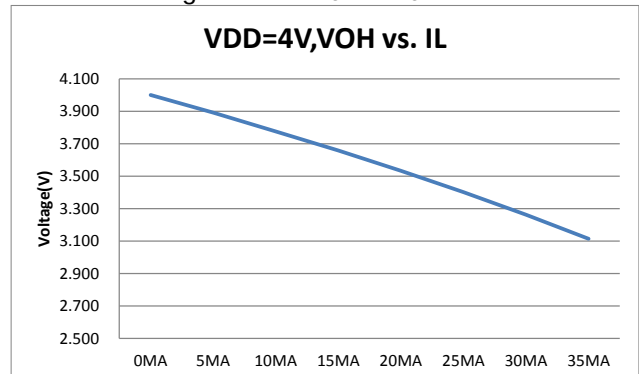


Figure 6.4-4 V_{IH}/V_{IL} vs. VDD

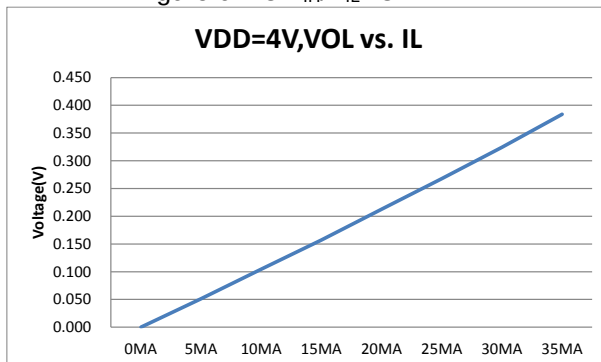


Figure 6.4-5 V_{IH}/V_{IL} vs. VDD

6.5. Reset(Brownout)

$T_A = 25^\circ\text{C}$, $V_{DD} = 3.0\text{V}$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
BOR1	Pulse length needed to accepted reset internally, t_{d-LVR1}		2			μS
	V_{DD} Start Voltage to accepted reset internally ($L \rightarrow H$), V_{HYS1}		1.0	1.35	1.65	V
	BOR1 current, I_{BOR1}			0.1	0.5	μA
	Temperature Drift			15		%
BOR2	Pulse length needed to accepted reset internally, t_{d-LVR2}		2			μS
	V_{DD} Start Voltage to accepted reset internally ($L \rightarrow H$), V_{HYS2} , and BOR_TH[2:0]:	000b	-10%	1.73	+10%	V
		001b	-10%	2.0	+10%	
		010b	-10%	2.22	+10%	
		011b	-10%	2.5	+10%	
		100b	-10%	2.72	+10%	
		101b	-10%	3.0	+10%	
		110b	-10%	3.63	+10%	
		111b	-10%	4.0	+10%	
	V_{DD} Start Voltage to accepted reset internally ($H \rightarrow L$), V_{LVR2} , and BOR_TH[2:0]:	000b	-10%	1.67	+10%	V
		001b	-10%	1.96	+10%	
		010b	-10%	2.17	+10%	
		011b	-10%	2.44	+10%	
		100b	-10%	2.69	+10%	
		101b	-10%	2.96	+10%	
		110b	-10%	3.58	+10%	
		111b	-10%	3.94	+10%	
	Hysteresis, $V_{HYS2-LVR2}$		25	60	90	mV
	BOR2 current, I_{BOR2}			10	15	μA
	Temperature Drift			3	5	%
MCLR	Pulse length needed as MCLR pin to accepted reset internally, t_{d-RST}		2			μS
	Input Voltage to accepted reset voltage			1.1		V
	Reset release voltage			2		V

BOR1/BOR2 : Brownout Reset 1/2
LVR : Low Voltage Reset of BOR
MCLR : External Reset pin

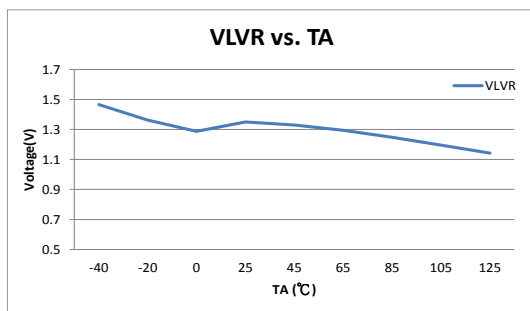


Figure 6.5-1 BOR1 vs. Temperature

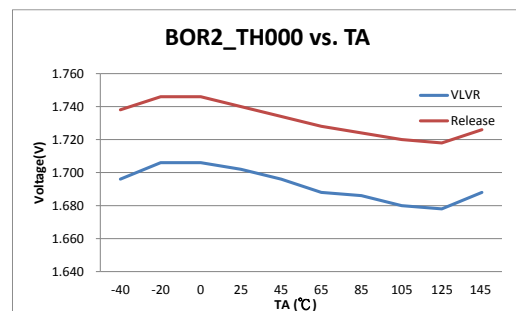


Figure 6.5-2 BOR2 vs. Temperature

6.6. Power System

 $T_A = 25^\circ\text{C}$, $V_{DD} = 3.0\text{V}$, unless otherwise noted

Sym.	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
VDDA	VDDA operation current, I _{VDDA}	I _L = 0mA	LDOC[2:0]=000b	20			uA
	Select VDDA output voltage	I _L = 0.1mA, VDD=5.5V	LDOC [2:0]=000b	-5%	2.4	+5%	V
			LDOC [2:0]=001b		2.6		
			LDOC [2:0]=010b		2.9		
			LDOC [2:0]=011b		3.3		
			LDOC [2:0]=100b		3.6		
			LDOC [2:0]=101b		4.0		
			LDOC [2:0]=110b		4.5		
			LDOC [2:0]=111b		5.0		
	I _L = 10mA, VDD=2.6V	LDOC [2:0]=000b	-6%	2.4	+5%		
Dropout voltage	VDD=2.9V, VDDA=2.9V mode (LDOC [2:0]=010b), IL = 10mA			200		mV	
Temperature drift	LDOC [2:0]=000b I _L = 0.1mA	T _A =-40℃~85℃		50		PPM/℃	
V _{DD} Voltage drift	LDOC [2:0]=000b	V _{DD} =2.2V~5.5V		±0.2		%/V	
ACM	operation current, I _{ACM}		ENVCM[0]=1b		50		uA
	Internal ADC common mode voltage, V _{ACM}	ENVCM[0]=1b	VCMS[0]=0b, SELVIN[0]=0b		VDDA/2		
			VCMS[0]=0b, SELVIN[0]=1b		1.2		V
		VCMS[0]=1b,		REFO			
VDDA : Adjust Voltage Regulator ACM : Internal ADC common mode voltage							

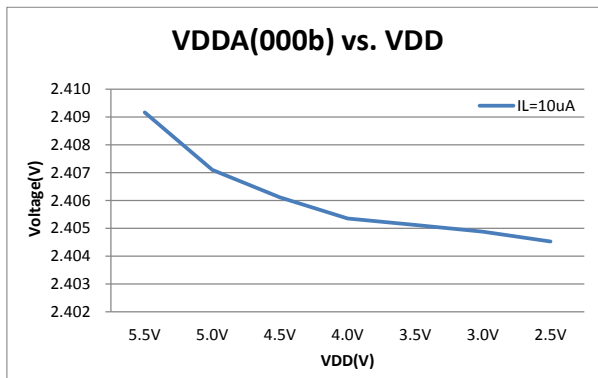


Figure 6.6-1 VDDA(000b) vs. VDD

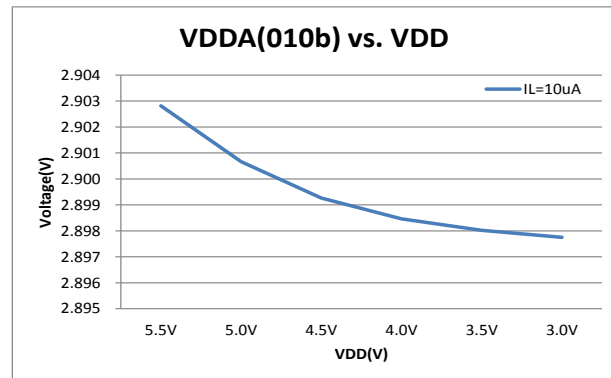


Figure 6.6-2 VDDA(010b) vs. VDD

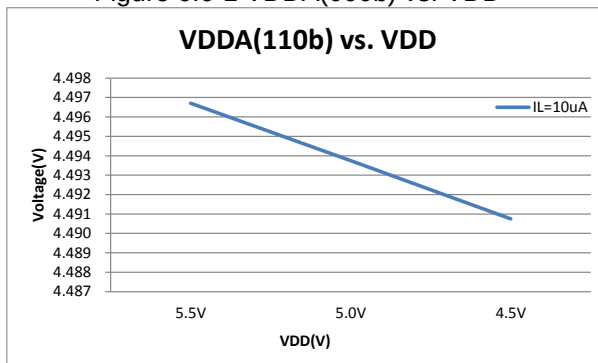


Figure 6.6-3 VDDA(110b) vs. VDD

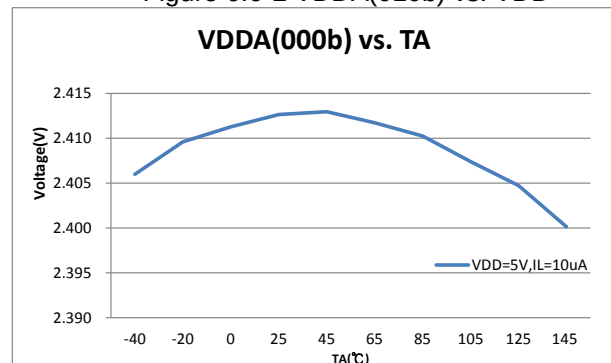


Figure 6.6-4 VDDA(000b) vs. Temperature

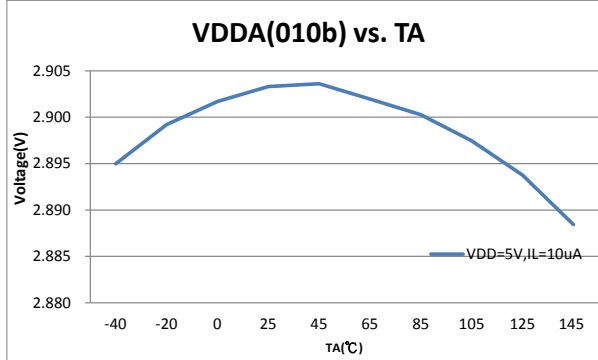


Figure 6.6-5 VDDA(010b) vs. Temperature

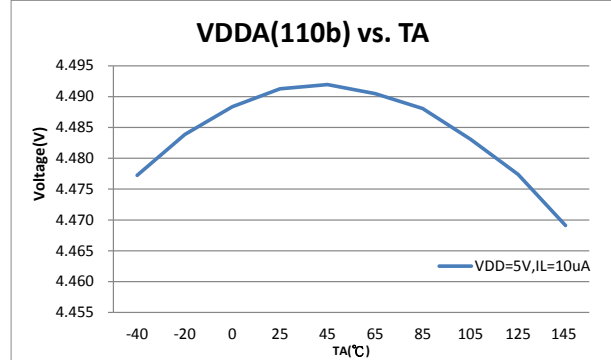


Figure 6.6-6 VDDA(110b) vs. Temperature

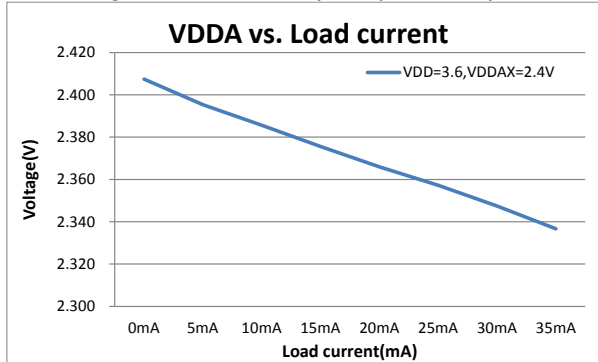


Figure 6.6-7 VDDA vs. Load current

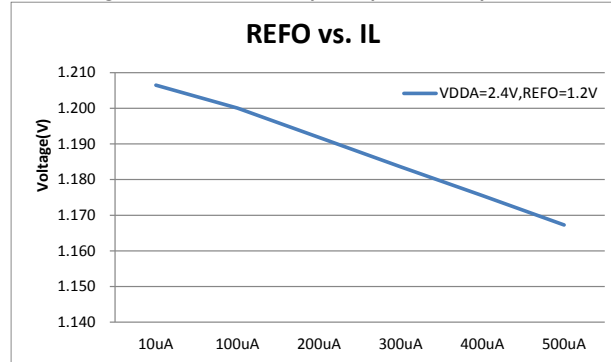


Figure 6.6-8 REFO vs. Load current

6.7. Multi-Comparator

 $T_A = 25^\circ\text{C}$, $V_{DD} = 3.0\text{V}$, unless otherwise noted.

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{MC}	Operation supply current	ENCMP[0]=1, CMPHS[0]=1b		5		μA
	Low Power Mode	ENCMP[0]=1, CMPHS [0]=0b		1		
V_{IC}	Common-mode input voltage		0		$V_{DD}-1$	V
V_{OS}	Offset voltage		-5		5	mV
V_{hys}	Input hysteresis		0	0.7	1.5	mV
V_{accy}	Reference Voltage	ENLDO[0]=1b, CPPS[1:0]=11b, VRSEL[0]=1b	1.15	1.2	1.25	V
	Temperature Drift			50		ppm/ $^\circ\text{C}$
	VDD Voltage drift			± 0.2		%/V
I_R	Multi-node resistor current	CPRL[0]=0b		10		μA
		CPRL[0]=1b		30		
	ENLDO[0]=1b, CPPS[1:0]=11b, CPRH [1:0]=01b, CPRL[0]=0b.	CPDA[4:0]=00011b	-5%	3.89	5%	V
		CPDA[4:0]=00100b		3.73		
		CPDA[4:0]=00101b		3.58		
		CPDA[4:0]=00110b		3.44		
		CPDA[4:0]=00111b		3.31		
		CPDA[4:0]=01000b		3.19		
		CPDA[4:0]=01001b		3.08		
		CPDA[4:0]=01010b		2.98		
		CPDA[4:0]=01011b		2.88		
		CPDA[4:0]=01100b		2.79		
		CPDA[4:0]=01101b		2.71		
		CPDA[4:0]=01110b		2.63		
		CPDA[4:0]=01111b		2.55		
		CPDA[4:0]=10000b		2.48		
		CPDA[4:0]=10001b		2.42		
		CPDA[4:0]=10010b		2.35		
		CPDA[4:0]=10011b		2.29		
		CPDA[4:0]=10100b		2.24		
		CPDA[4:0]=10101b		2.18		
		CPDA[4:0]=10110b		2.13		
		CPDA[4:0]=10111b		2.08		
		CPDA[4:0]=11000b		2.03		
		CPDA[4:0]=11001b		1.99		
		CPDA[4:0]=11010b		1.94		
		CPDA[4:0]=11011b		1.90		
		CPDA[4:0]=11100b		1.86		
		CPDA[4:0]=11101b		1.82		
	CPDA[4:0]=00000b~00010b, and 11110b~11111b (reserved)					

LVD : Low Voltage Detect.

6.8. $\Sigma\Delta$ ADC, Power Supply and recommended operating conditions

$T_A = 25^\circ\text{C}$, $V_{DD} = 3.0\text{V}$, $V_{DDA} = 2.4\text{V}$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{\Sigma\Delta\text{ADC}}$	Supply Voltage at V_{DDA}	ENLDO[0]=0	2.4		5.5	V
$f_{\Sigma\Delta\text{ADC}}$	Modulator sample frequency, ADC_CK		125	1000	1200	KHz
	Over Sample Ratio, OSR		64		65536	
$I_{\Sigma\Delta\text{ADC}}$	Operation supply current	ENAD1 [0]=1 GAIN =16, $\text{ADC_CK}=1\text{MHz}$		260		μA

6.9. $\Sigma\Delta$ ADC, Performance

$T_A = 25^\circ\text{C}$, $V_{DD} = 3.3\text{V}$, $V_{DDA} = 2.4\text{V}$, $V_{VR} = (V_{DDA} - V_{SS})/2$, $\text{GAIN} = 1$, $f_{\Sigma\Delta\text{ADC}} = 1000\text{KHz}$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
INL	Integral Nonlinearity(INL)	$V_{DDA} = 2.4\text{V}$, $V_{VR} = V_{DDA}/2$, $\Delta\text{SI} = \pm 450\text{mV}$		± 0.003	± 0.01	%FSR
	No Missing Codes ³	$\text{ADC_CK} = 1000\text{KHz}$, $\text{OSR}[3:0] = 0000\text{b}$	23			Bits
$G_{\Sigma\Delta\text{ADC}}$	Temperature drift Gain x16	$T_A = -40^\circ\text{C} \sim 85^\circ\text{C}$		20		$\text{ppm}/^\circ\text{C}$
E_{OS}	Offset error of Full Scale Rang input voltage range with Chopper	$\Delta\text{AI} = 0\text{V}$ $\Delta\text{VR} = 1.2\text{V}$ $\text{DCSET}[3:0] = 0000\text{b}$ * ΔAI is external short Gain Normalized	Gain=2		1	%FSR
	Offset temperature drift with Chopper mode		GAIN=1	0.021		$\mu\text{V}/^\circ\text{C}$
			GAIN=2	0.026		
			GAIN=4	0.03		
			GAIN=16	0.45		
$\text{CM}_{\Sigma\Delta\text{ADC}}$	Common-mode rejection	$V_{\text{CM}} = 0.7\text{V}$ to 1.7V , $V_{\text{VR}} = 1.0\text{V}$	$V_{\text{SI}} = 0\text{V}$, GAIN=1	90		dB
			$V_{\text{SI}} = 0\text{V}$, GAIN=16	75		dB
PSRR	DC power supply rejection	$V_{DDA} = 3.0\text{V}$, $\Delta V_{DDA} = \pm 100\text{mV}$, $V_{\text{VR}} = 1.0\text{V}$, $V_{\text{SI}} = 1.2\text{V}$, $V_{\text{SS}} = 1.2\text{V}$,	GAIN=1	75		dB
			GAIN=16			dB

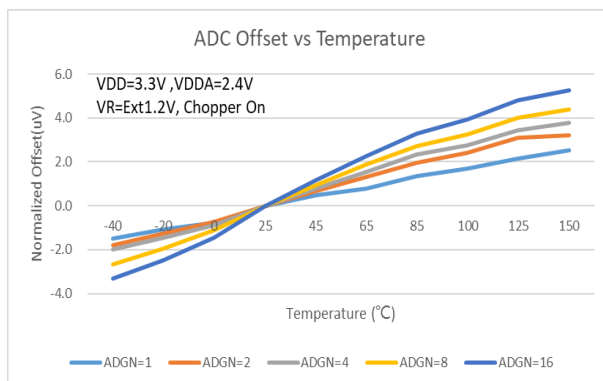


Figure 6.11-1 ADC Offset drift with Temperature

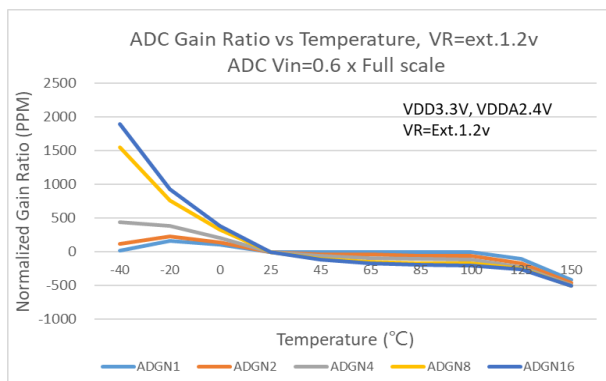


Figure 6.11-2 ADC Gain drift with Temperature

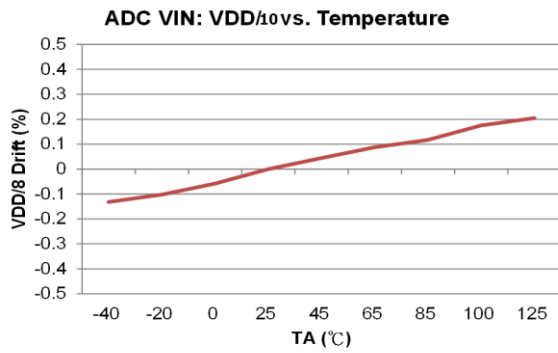


Figure 6.11-3 VDD/10 drift with Temperature

6.10. $\Sigma\Delta$ ADC Noise Performance

HY17M26 for $\Sigma\Delta$ ADC provide important input noise specifications. Table 6.12-1 lists typical noise specification sheet and Gain, Output rate, and the largest single-ended input voltage relationship. Test conditions were set at the external input signal is a short circuit, a reference voltage $V_{REF}=(V_{DDA}-V_{SS})/2=1.2V$, and 1024 records were sampled.

<i>ENOB(RMS) with OSR/GAIN at A/D Clock=1MHz, VDDA=2.4V, VREF=V12, Chopper Off</i>													
OSR					64	128	256	512	1024	2048	4096	8196	16384
Output rate(Hz)					15625	7813	3906	1953	977	488	244	122	61
Gain	=	PGAGN	x	ADGN	32768	16384	8192	4096	2048	1024	512	256	128
0.25	=	off	x	0.25	14.47	16.21	16.89	16.48	17.62	18.62	18.97	19.43	20.01
0.5	=	off	x	0.5	14.39	16.17	16.84	16.55	17.85	18.36	18.92	19.39	19.83
1	=	off	x	1	14.16	16.13	16.8	16.67	18.01	18.2	18.72	19.2	19.69
2	=	off	x	2	13.83	15.91	16.49	16.45	17.5	17.99	18.32	18.77	19.39
4	=	off	x	4	13.19	15.68	16.27	16.55	17.21	17.8	18.06	18.36	19.05
8	=	off	x	8	13.99	15.4	15.96	16.16	16.89	17.25	17.24	17.65	18.57
16	=	off	x	16	11.96	14.91	15.44	15.27	16.12	16.41	16.27	16.59	17.76

<i>RMS Noise(uV) with OSR/GAIN at A/D Clock=1MHz, VDDA=2.4V, VREF=V12, Chopper Off</i>													
OSR					64	128	256	512	1024	2048	4096	8196	16384
Output rate(Hz)					15625	7813	3906	1953	977	488	244	122	61
Gain	=	PGAGN	x	ADGN	32768	16384	8192	4096	2048	1024	512	256	128
0.25	=	off	x	0.25	423.20	126.66	78.98	104.91	47.63	23.85	18.74	13.59	9.12
0.5	=	off	x	0.5	224.02	65.01	40.84	49.96	20.25	14.30	9.66	6.98	5.14
1	=	off	x	1	130.78	33.53	20.97	23.02	9.10	7.99	5.58	3.99	2.83
2	=	off	x	2	82.66	19.56	13.00	13.39	6.47	4.60	3.68	2.68	1.75
4	=	off	x	4	64.21	11.45	7.58	6.25	3.95	2.63	2.19	1.78	1.11
8	=	off	x	8	18.44	6.96	4.70	4.09	2.47	1.93	1.94	1.46	0.77
16	=	off	x	16	37.63	4.89	3.38	3.78	2.11	1.72	1.90	1.52	0.68

Table 6.12-1(a) $\Sigma\Delta$ ADC ENOB and RMS Noise Table

<i>ENOB(RMS) with OSR/GAIN at A/D Clock=1MHz, VDDA=2.4V, VREF=V12, Chopper On</i>													
OSR					64	128	256	512	1024	2048	4096	8196	16384
Output rate(Hz)					5208	2604	1302	651	326	163	122	61	31
Gain	=	PGAGN	x	ADGN	2604	1302	651	326	163	122	61	31	15
0.25	=	off	x	0.25	15.58	17.05	17.64	18.13	18.61	19.3	19.63	20.15	20.63
0.5	=	off	x	0.5	15.62	16.81	17.64	18.06	18.67	19.16	19.52	19.92	20.43
1	=	off	x	1	15.45	16.69	17.56	17.99	18.5	18.92	19.27	19.82	20.29
2	=	off	x	2	15.43	16.3	17.25	17.63	18.21	18.53	18.8	19.29	20.05
4	=	off	x	4	15.34	16.18	16.9	17.43	17.8	18.15	18.27	18.91	19.84
8	=	off	x	8	15.07	15.48	16.52	16.8	17.3	17.45	17.55	18.05	19.26
16	=	off	x	16	14.91	14.53	15.89	16.18	16.43	16.4	16.35	16.87	18.71

<i>ENOB(RMS) with OSR/GAIN at A/D Clock=1MHz, VDDA=2.4V, VREF=V12, Chopper On</i>													
OSR					64	128	256	512	1024	2048	4096	8196	16384
Output rate(Hz)					5208	2604	1302	651	326	163	122	61	31
Gain	=	PGAGN	x	ADGN	2604	1302	651	326	163	122	61	31	15
0.25	=	off	x	0.25	195.81	70.91	46.96	33.52	24.07	14.90	11.87	8.25	5.93
0.5	=	off	x	0.5	95.23	41.74	23.56	17.53	11.50	8.19	6.37	4.85	3.39
1	=	off	x	1	53.79	22.65	12.44	9.24	6.47	4.86	3.79	2.59	1.87
2	=	off	x	2	27.26	14.83	7.67	5.91	3.95	3.17	2.64	1.88	1.11
4	=	off	x	4	14.51	8.09	4.91	3.39	2.64	2.06	1.90	1.22	0.64
8	=	off	x	8	8.75	6.58	3.20	2.62	1.86	1.68	1.57	1.11	0.48
16	=	off	x	16	4.88	6.32	2.47	2.03	1.70	1.74	1.79	1.26	0.35

Table 6.12-1(b) $\Sigma\Delta$ ADC ENOB and RMS Noise Table

The RMS Noise are referred to the input. The Effective Number of Bits (ENOB(RMS Bit)) is defined as:

$$\text{ENOB(RMS)} = \frac{\ln\left(\frac{\text{FSR}}{\text{RMS Noise}}\right)}{\ln(2)}$$

$$\text{RMS Noise} = \frac{\left(2 \times \text{VREF} \times \sqrt{\sum_{k=1}^{1024} (\text{ADO}[k] - \text{Average})^2}\right)}{2^{23}}$$

Where FSR (Full - Scale Range) = $2 \times \text{VREF}/\text{Gain}$.

$$\text{Average} = \frac{\sum_{k=1}^{1024} (\text{ADO}[k])}{1024}$$

6.11. $\Sigma\Delta$ ADC ,Temperature Sensor

$T_A = 25^\circ\text{C}$, $V_{DD} = 3.0\text{V}$, $V_{DDA} = 2.4\text{V}$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
TC_S	Sensor temperature drift			173		$\mu\text{V}/^\circ\text{C}$
KT	Absolute Temperature Scale 0°K			-277		$^\circ\text{C}$
TC_{ERR}	One point calibrate error temperature	Calibration at 25°C of $-40^\circ\text{C} \sim 85^\circ\text{C}$		± 2		$^\circ\text{C}$

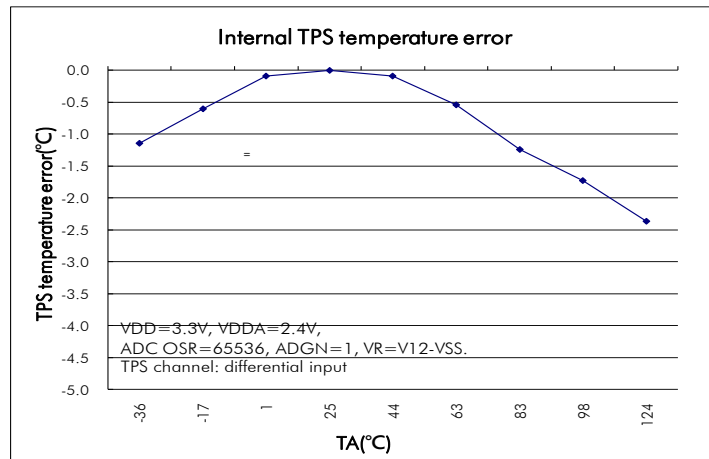


Figure 6.13-1 Internal Temperature Sensor (TPS) temperature error

6.12. MTP Memory

TA = -40°C~85°C, VDD=3V, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max	Unit
Main MTP Program Memory/ Build-In EPROM Data Memory						
V _{DD}	Read/Write/Program/Erase Memory Operation supply Voltage		2.75		5.5	V
I _{BIEE}	Read/Write/Program/Erase Memory Operation supply current				22	mA
T _{DART}	Data retention time		10			Years
C _{MAIN}	Endurance cycles at main MTP block		100			Cycles
C _{EPROM}	Endurance cycles at EPROM block		100			Cycles

7. Ordering Information

Device No. ¹	Package Type	Pins	Package Drawing		Code No. ²	Shipment Packing Type	Unit Q'ty	Material Composition	MSL3
HY17M26-NS32	QFN	32	N	S32	000	Tape & Reel	5000	Green ⁴	MSL-3
HY17M26-ES28	SSOP	28	E	S28	000	Tube	50	Green ⁴	MSL-3
HY17M26-ES28	SSOP	28	E	S28	000	Tape & Reel	3000	Green ⁴	MSL-3
HY17M26-E016	SSOP	16	E	016	000	Tube	100	Green ⁴	MSL-3
HY17M26-E016	SSOP	16	E	016	000	Tape & Reel	2500	Green ⁴	MSL-3

¹ Device No.: Model No. – Package Type Description – Code (Blank Code/ Standard/Customized Programming Code)

Ex: You request blank code in QFN32 package. The device No. will be HY17M26-N032. and please clearly indicate the shipment packing type when placing orders.

Ex: Your customized programming code is 009 and you require products in QFN32 package. The device No. will be HY17M26-N032-009. and please clearly indicate the shipment packing type when placing orders.

Ex: You request blank code in SSOP28 package. The device No. will be HY17M26-ES28. and please clearly indicate the shipment packing type when placing orders.

Ex: Your customized programming code is 009 and you require products in SSOP28 package. The device No. will be HY17M26-ES28-009. and please clearly indicate the shipment packing type when placing orders.

Ex: You request blank code in SSOP16 package. The device No. will be HY17M26-E016. and please clearly indicate the shipment packing type when placing orders.

Ex: Your customized programming code is 007 and you require products in SSOP16 package. The device No. will be HY17M26-E016-007. and please clearly indicate the shipment packing type when placing orders.

² Code

“001”~ “999” is standard or customized programming code. Blank code does not have these numbers.

³ MSL:

The Moisture Sensitivity Level ranking conforms to IPC/JEDEC J-STD-020 industry standard categorization. The products are processed, packed, transported and used with reference to IPC/JEDEC J-STD-033.

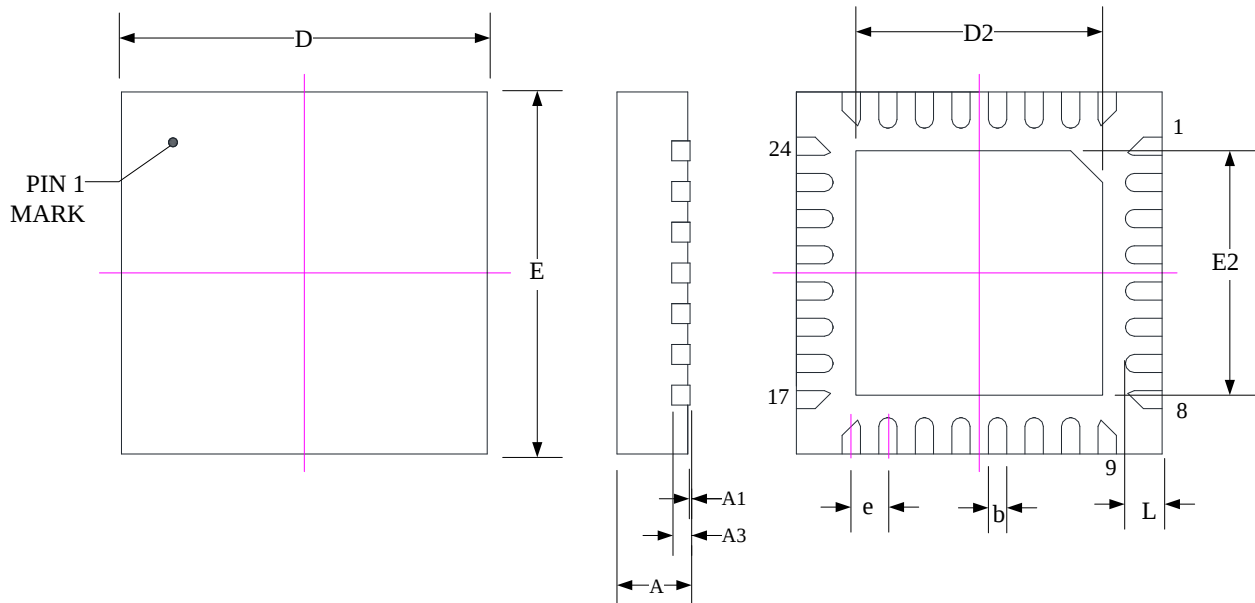
⁴ Green (RoHS & no Cl/Br):

HYCON products are Green products that compliant with RoHS directive and are Halogen free (Br<900ppm or Cl<900ppm or (Br+Cl)<1500ppm) °

8. Package Information

8.1. QFN32(NS32)

8.1.1. Package Dimensions QFN32(4x4x0.55)

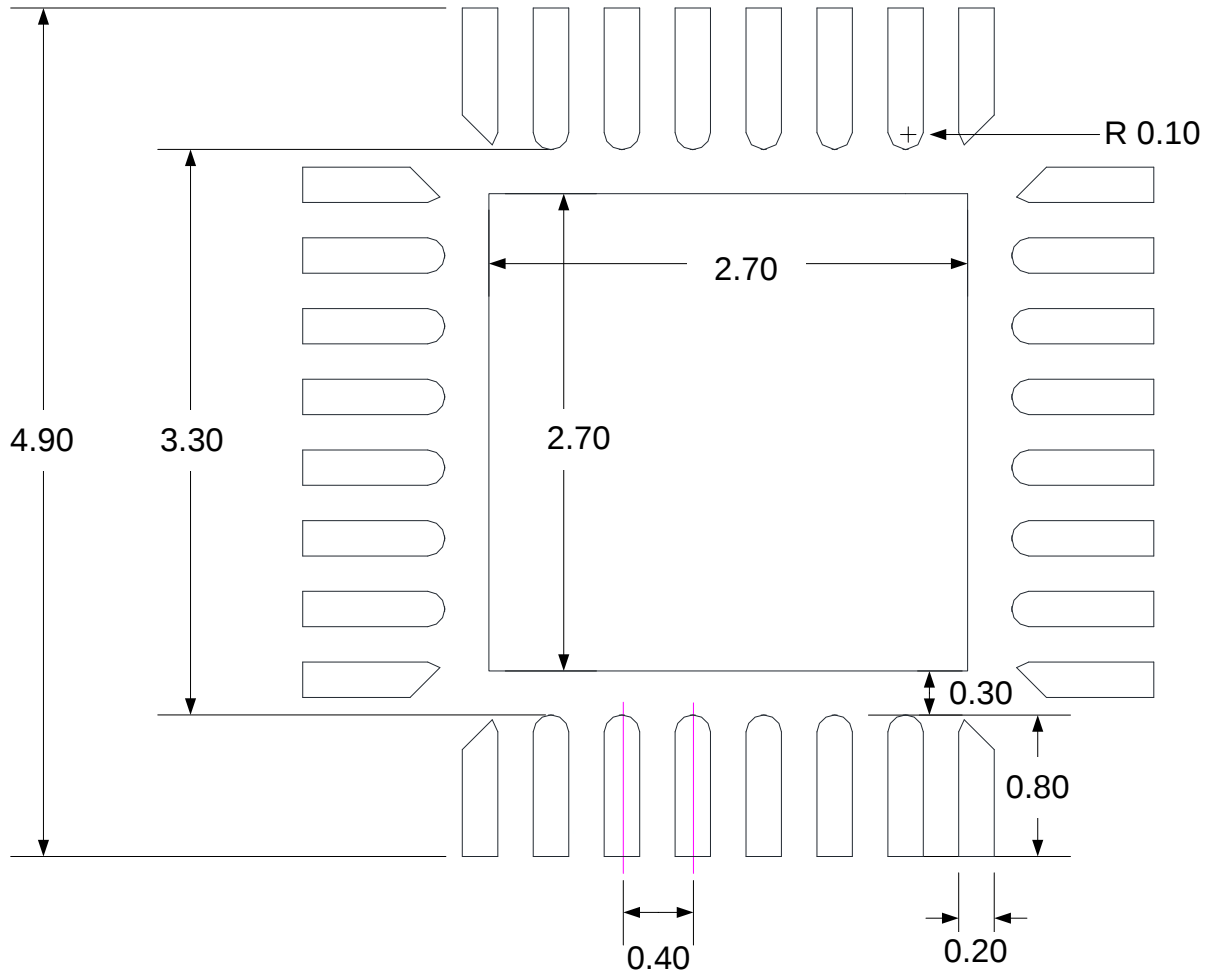


SYMBOLS	MIN	NOM	MAX
A	0.50	0.55	0.60
A1	0.00	0.02	0.05
A3	0.15 REF.		
b	0.15	0.20	0.25
D	3.90	4.00	4.10
E	3.90	4.00	4.10
D2	2.65	2.70	2.75
E2	2.65	2.70	2.75
L	0.25	0.30	0.35
e	0.40 BASIC		

Note:

1. All dimensions refer to JEDEC OUTLINE MO-220.
2. Do not include Mold Flash or Protrusions.
3. Unit: mm.
4. https://www.hycontek.com/hy_mcu/QFN_DFN_PCB.pdf

8.1.2. Land Pattern Design Recommendations



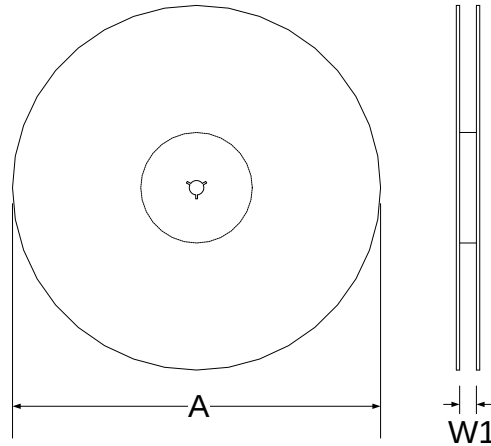
Note:

1. Publication IPC-7351 is recommended for alternate designs.
2. https://www.hycontek.com/wp-content/uploads/QFN_DFN_PCB.pdf
3. Unit: mm.

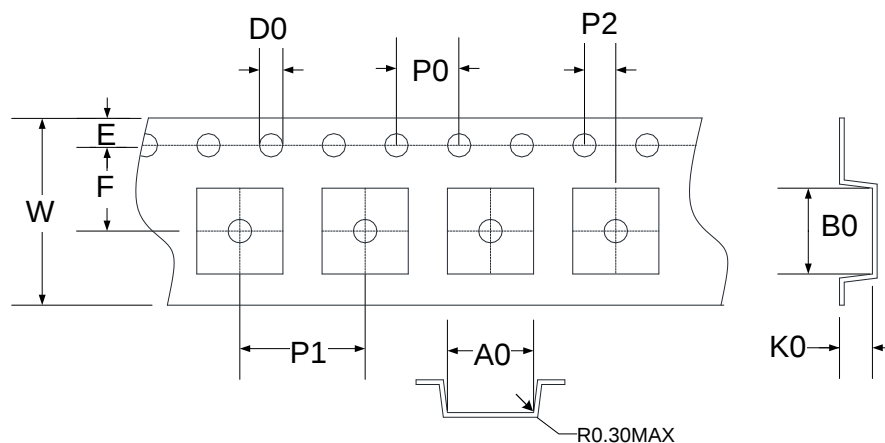
8.1.3. Tape & Reel Information

8.1.3.1. Reel Dimensions

Unit: mm



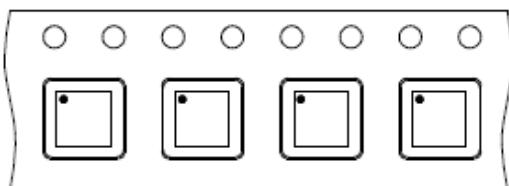
8.1.3.2. Carrier Tape Dimensions



SYMBOLS	Reel Dimensions		Carrier Tape Dimensions									
	A	W1	A0	B0	K0	P0	P1	P2	E	F	D0	W
Spec.	330	12.5	4.35	4.35	1.10	4.00	8.00	2.00	1.75	5.50	1.50	12.00
Tolerance	+6/-3	+1.5/-0	±0.10	±0.10	±0.10	±0.10	±0.10	±0.05	±0.10	±0.05	+0.1/-0	±0.30

Note: 10 Sprocket hole pitch cumulative tolerance is ± 0.20 mm.

8.1.3.3. Pin1 direction

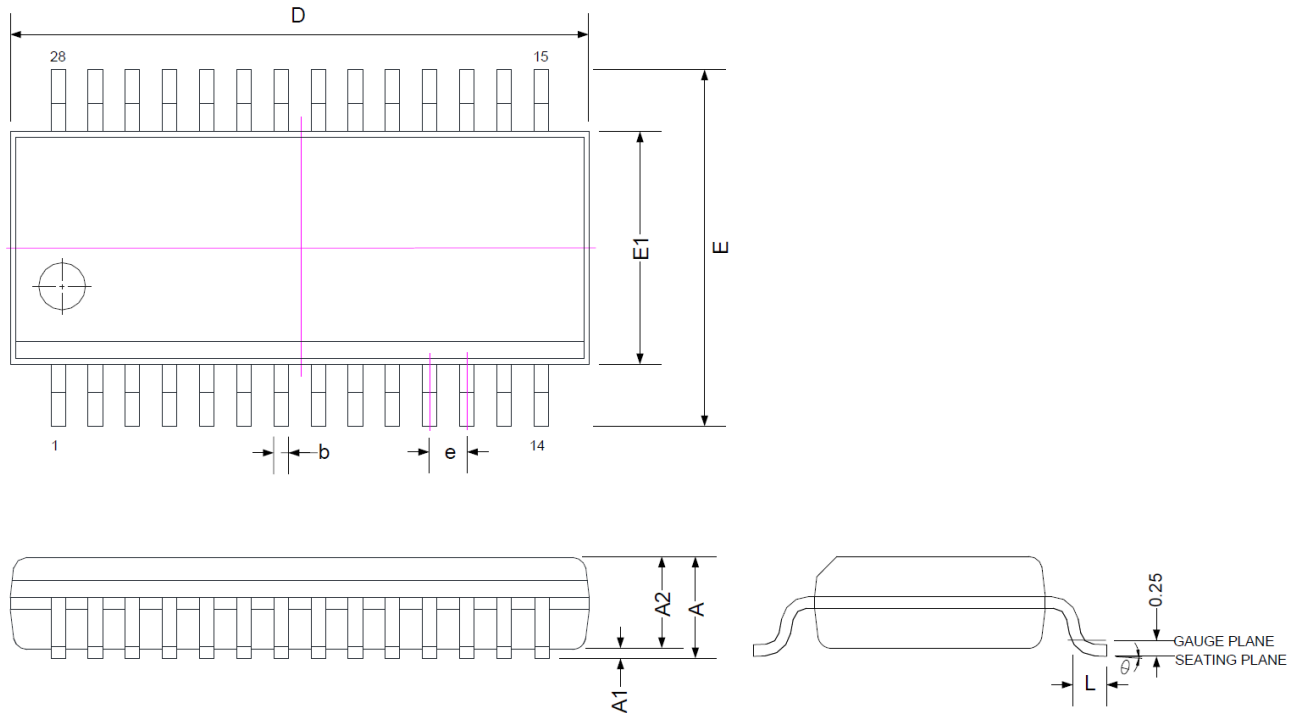


HY17M26

8-bit RISC-like Mixed Signal Microcontrollers with
Embedded High Resolution $\Sigma\Delta$ ADC for bridge sensor application

8.2. SSOP28(ES28)

8.2.1. Package Dimensions SSOP28(150mil)



SYMBOLS	MIN	NOM	MAX
A	1.34	1.63	1.75
A1	0.10	0.15	0.25
A2	-	-	1.50
b	0.20	-	0.30
c	0.18	-	0.25
D	9.80	9.91	10.01
E1	3.81	3.91	3.99
E	5.79	5.99	6.20
L	0.41	0.64	1.27
e	0.635 BASIC		
θ°	0	-	8

Note:

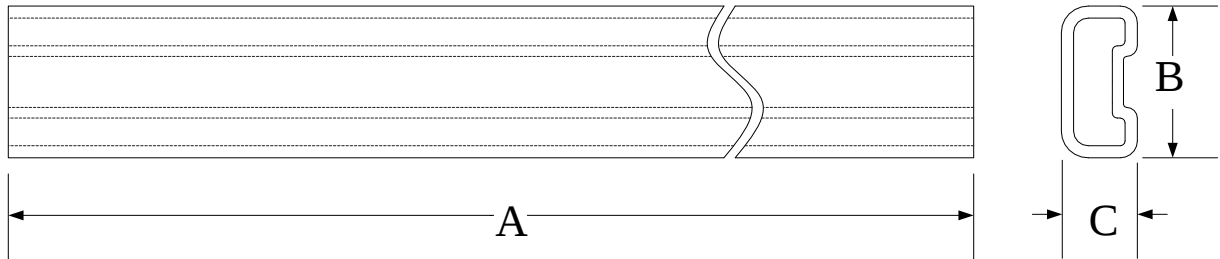
1. All dimensions refer to JEDEC OUTLINE MO-137.
2. Do not include Mold Flash or Protrusions.
3. Unit: mm.

HY17M26

8-bit RISC-like Mixed Signal Microcontrollers with
Embedded High Resolution $\Sigma\Delta$ ADC for bridge sensor application

8.2.2. Tube Dimensions SSOP28(150mil)

Unit : mm

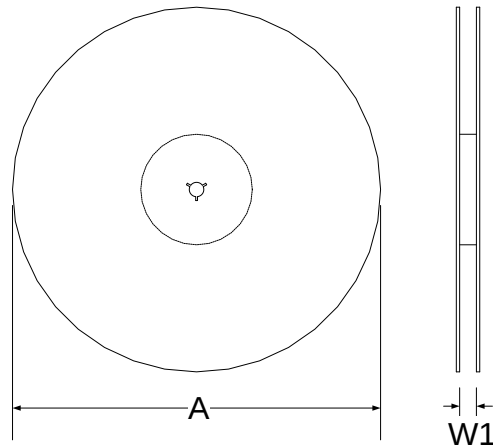


SYMBOLS	A	B	C
Spec.	529.6±1.0	8.001±0.127	3.937±0.127

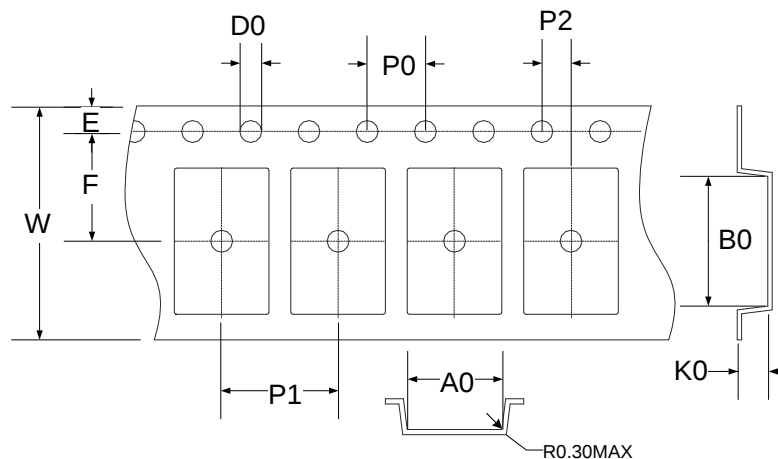
8.2.3. Tape & Reel Information

8.2.3.1. Reel Dimensions

Unit: mm



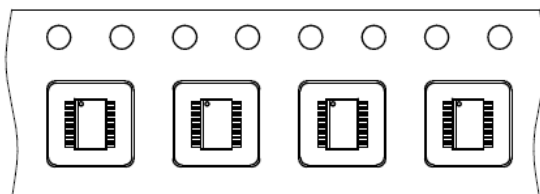
8.2.3.2. Carrier Tape Dimensions



SYMBOLS	Reel Dimensions		Carrier Tape Dimensions									
	A	W1	A0	B0	K0	P0	P1	P2	E	F	D0	W
Spec.	330	16.5	6.50	10.30	2.10	4.00	8.00	2.00	1.75	7.50	1.50	16.00
Tolerance	+6/-3	+1.5/-0	±0.10	±0.10	±0.10	±0.10	±0.10	±0.05	±0.10	±0.10	+0.1/-0	±0.30

Note: 10 Sprocket hole pitch cumulative tolerance is ± 0.20 mm.

8.2.3.3. Pin1 direction

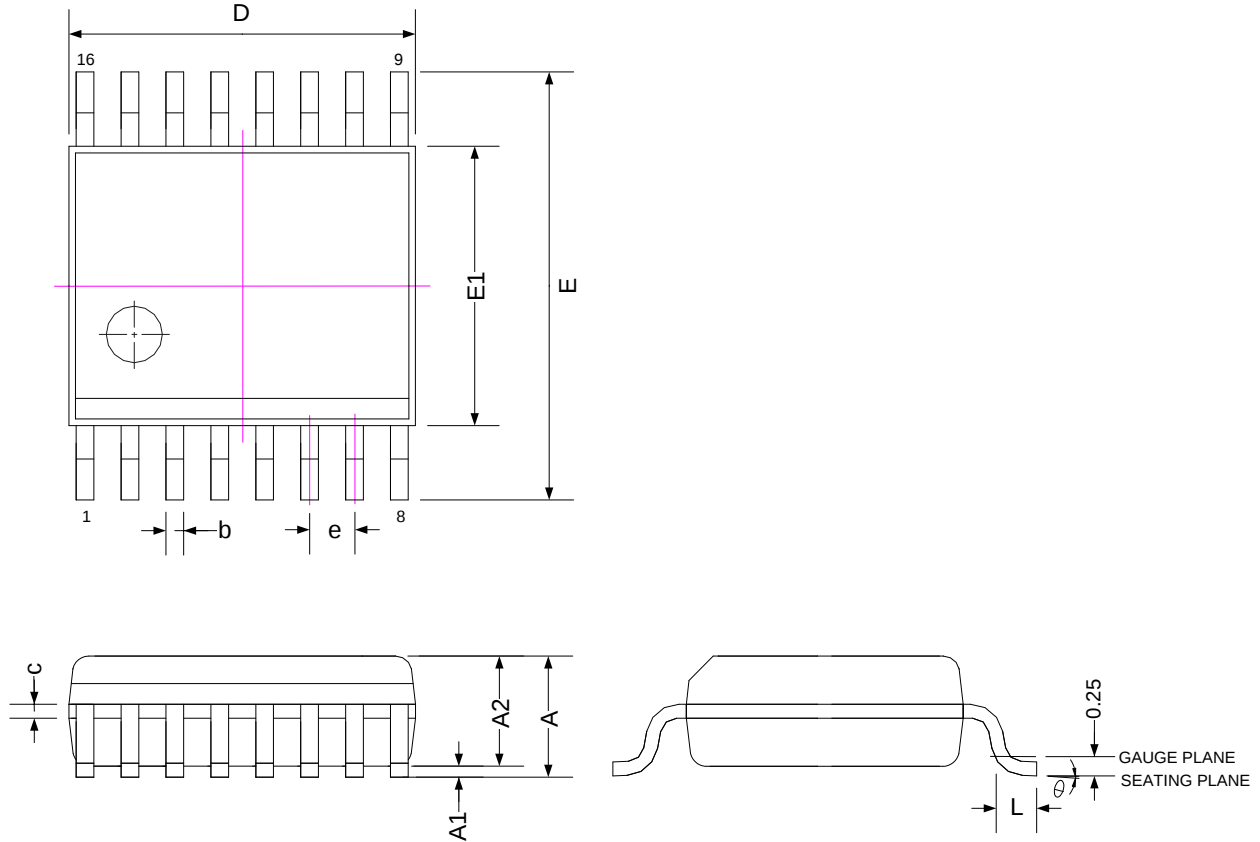


HY17M26

8-bit RISC-like Mixed Signal Microcontrollers with
Embedded High Resolution $\Sigma\Delta$ ADC for bridge sensor application

8.3. SSOP16(E016)

8.3.1. Package Dimensions SSOP16(150mil)



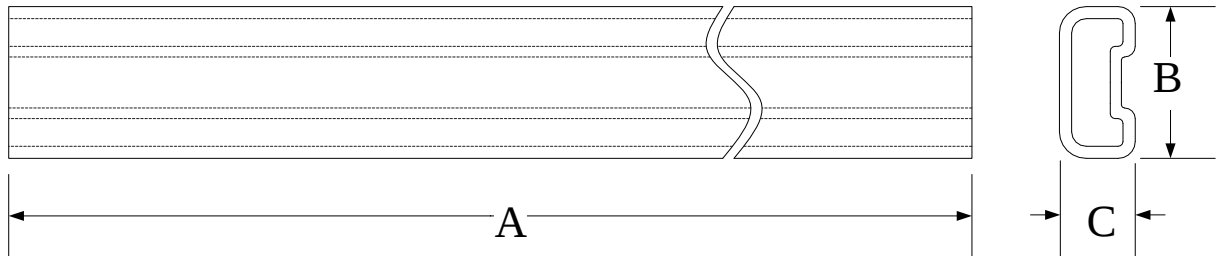
SYMBOLS	MIN	NOM	MAX
A	-	-	1.75
A1	0.10	0.15	0.25
A2	-	-	1.50
b	0.20	-	0.30
c	0.18	-	0.25
D	4.80	4.90	5.00
E1	3.81	3.91	3.99
E	5.79	5.99	6.20
L	0.41	-	1.27
e	0.635 BASIC		
θ°	0	-	8

Note:

1. All dimensions refer to JEDEC OUTLINE MO-137.
2. Do not include Mold Flash or Protrusions.
3. Unit: mm.

8.3.2. Tube Dimensions SSOP16(150mil)

Unit : mm



Type 1:

SYMBOLS	A	B	C
Spec.	521.0±1.0	7.747±0.15	3.810±0.15

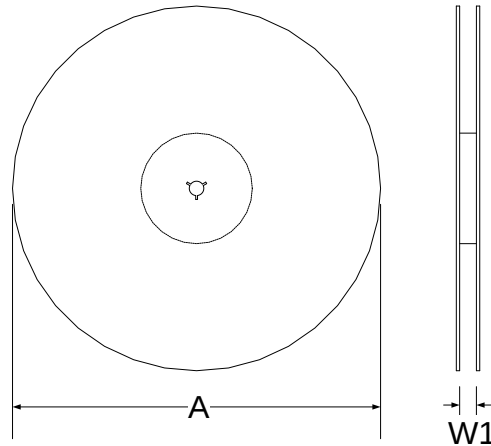
Type 2:

SYMBOLS	A	B	C
Spec.	521.0±1.0	7.874 REF.	3.810 REF.

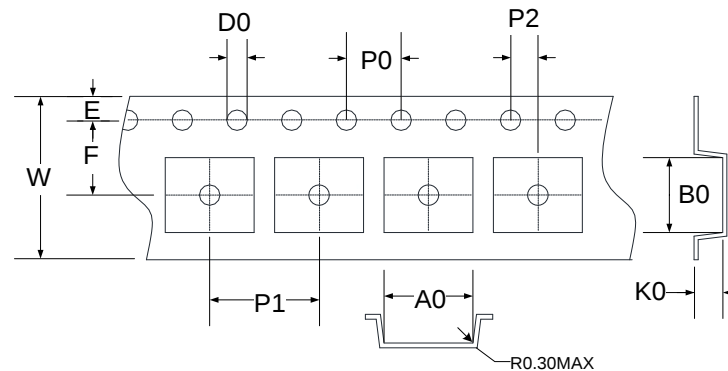
8.3.3. Tape & Reel Information

8.3.3.1. Reel Dimensions-Type1

Unit: mm



8.3.3.2. Carrier Tape Dimensions

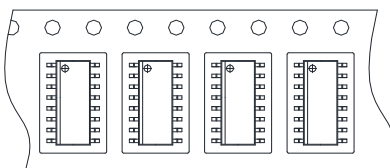


SYMBOLS	Reel Dimensions		Carrier Tape Dimensions									
	A	W1	A0	B0	K0	P0	P1	P2	E	F	D0	W
Spec.	330	12.5	6.90	5.40	2.00	4.00	8.00	2.00	1.75	5.50	1.50	12.00
Tolerance	+6/-3	+1.5/-0	±0.10	±0.10	±0.10	±0.10	±0.10	±0.05	±0.10	±0.05	+0.1/-0	±0.30

Note: 10 Sprocket hole pitch cumulative tolerance is ± 0.20 mm.

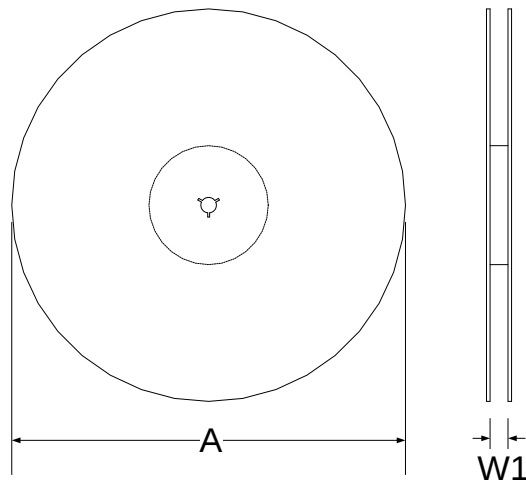
Unit : mm

8.3.3.3. Pin1 direction

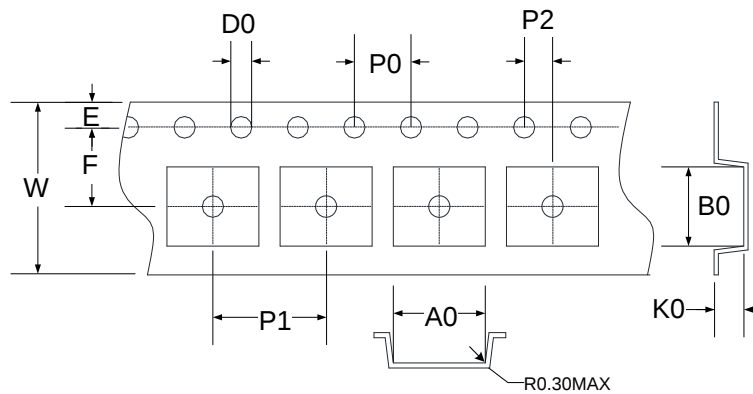


8.3.3.4. Reel Dimensions-Type2

Unit: mm



8.3.3.5. Carrier Tape Dimensions

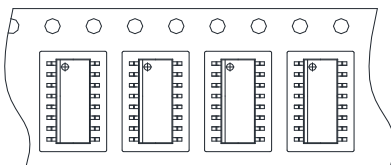


SYMBOLS	Reel Dimensions		Carrier Tape Dimensions									
	A	W1	A0	B0	K0	P0	P1	P2	E	F	D0	W
Spec.	330	12.5	6.50	5.20	2.10	4.00	8.00	2.00	1.75	5.50	1.50	12.00
Tolerance	+6/-3	+1.5/-0	±0.10	±0.10	±0.10	±0.10	±0.10	±0.05	±0.10	±0.05	+0.1/-0	±0.30

Note: 10 Sprocket hole pitch cumulative tolerance is ± 0.20 mm.

Unit : mm

8.3.3.6. Pin1 direction



9. Revision Record

Major differences are stated thereafter.

Version	Page	Date	Revision Summary
V01	All	2021/12/07	First edition
V02	All	2022/04/08	1. Modify QFN32 product packaging quantity. 2. Remove Die package type. 3. Modify QFN32 package dimension. 4. Modify the LPO typical value from 15kHz to 14.5kHz (+/- 20%). 5. Modify the Reset release voltage of MCLR from 1.6V to 2V. 6. Modify the maximum and minimum of the BOR2 specification are revised to +/-10%. 7. Modify the register list.
V03	5 6 38 48	2022/09/30	1. Modify the product specifications list 2. Correct the QFN32 pin diagram (pin 20 is ECK0, pin 21 is EDIO0). 3. Modify the minimum of the V_{OH} to $V_{DD}-0.5V$. 4. Modify the chapter 6.12 name and description
V04	All	2023/01/31	1. Modify the Write/Erase cycle times of MTP/Build-In EPROM. Before the modification, the number of MTP the Write/Erase cycle times is 1K times. After the modification, the number of MTP the Write/Erase cycle times is 100 times. Before the modification, the number of Build-In EPROM the Write/Erase cycle times is 1K times. After the modification, the number of Build-In EPROM the Write/Erase cycle times is 100 times. 2. Modify the current Typ. value of BOR1 to 0.1uA.